

# Datasheet

## 1. Features

- Dual ADC with 8-bit Resolution
- 500 Msp/s Sampling Rate per Channel, 1 Gsp/s in interleaved Mode
- Single or 1:2 Demultiplexed Output
- LVDS Output Format (100Ω)
- 500 mVpp Analog Input (Differential Only)
- Differential or Single-ended 50Ω PECL/LVDS Compatible Clock Inputs
- Power Supply: 3.3V (Analog), 3.3V (Digital), 2.25V (Output)
- LQFP144 or LQFP-ep 144L Green packages
- Temperature Range:
  - 0°C < T<sub>amb</sub> < 70°C (Commercial Grade)
  - -40°C < T<sub>amb</sub> < 85°C (Industrial Grade)
- 3-wire Serial Interface
  - 16-bit Data, 3-bit Address
  - 1:2 or 1:1 Output Demultiplexer Ratio Selection
  - Full or Partial Standby Mode
  - Analog Gain (±1.5 dB) Digital Control
  - Input Clock Selection
  - Analog Input Switch Selection
  - Binary or Gray Logical Outputs
  - Synchronous Data Ready Reset
  - Data Ready Delay Adjustable on Both Channels
  - interleaving Functions:
    - Offset and Gain (Channel to Channel) Calibration
    - Digital Fine SDA (Fine Sampling Delay Adjust) on One Channel
  - Internal Static or Dynamic Built-In Test (BIT)

## 2. Performance

- Low Power Consumption: 0.7W per Channel
- Power Consumption in Standby Mode: 120 mW
- 1 GHz Full Power Input Bandwidth (-3 dB)
- SNR = 45 dB Typ (7.2 ENOB), THD = -53 dBc, SFDR = -56 dBc at F<sub>s</sub> = 500 Msp/s  
F<sub>in</sub> = 250 MHz
- 2-tone IMD3: -54 dBc (249 MHz, 251 MHz) at 500 Msp/s
- DNL = 0.25 LSB, INL = 0.5 LSB
- Low Bit Error Rate (10<sup>-18</sup>) at 500 Msp/s

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### 3. Application

- Digital Oscilloscopes
- Communication Receivers (I/Q)
- Direct RF Down Conversion
- High Speed Data Acquisition
- Radar/ECM

### 4. Description

The AT84AD004B is a monolithic dual 8-bit analog-to-digital converter, offering low 1.4W power consumption and excellent digitizing accuracy. It integrates dual on-chip track/holds that provide an enhanced dynamic performance with a sampling rate of up to 500 Msps and an input frequency bandwidth of 1 GHz. The dual concept, the integrated demultiplexer and the easy interleaving mode make this device user-friendly for all dual channel applications, such as direct RF conversion or data acquisition. The *smart* function of the 3-wire serial interface eliminates the need for external components, which are usually necessary for gain and offset tuning and setting of other parameters, leading to space and power reduction as well as system flexibility.

### 5. Functional Description

The AT84AD004B is a dual 8-bit 500 Msps ADC based on advanced high-speed BiCMOS technology.

Each ADC includes a front-end analog multiplexer followed by a Sample and Hold (S/H), and an 8-bit flash-like architecture core analog-to-digital converter. The output data is followed by a switchable 1:1 or 1:2 demultiplexer and LVDS output buffers (100 $\Omega$ ).

Two over-range bits are provided for adjustment of the external gain control on each channel.

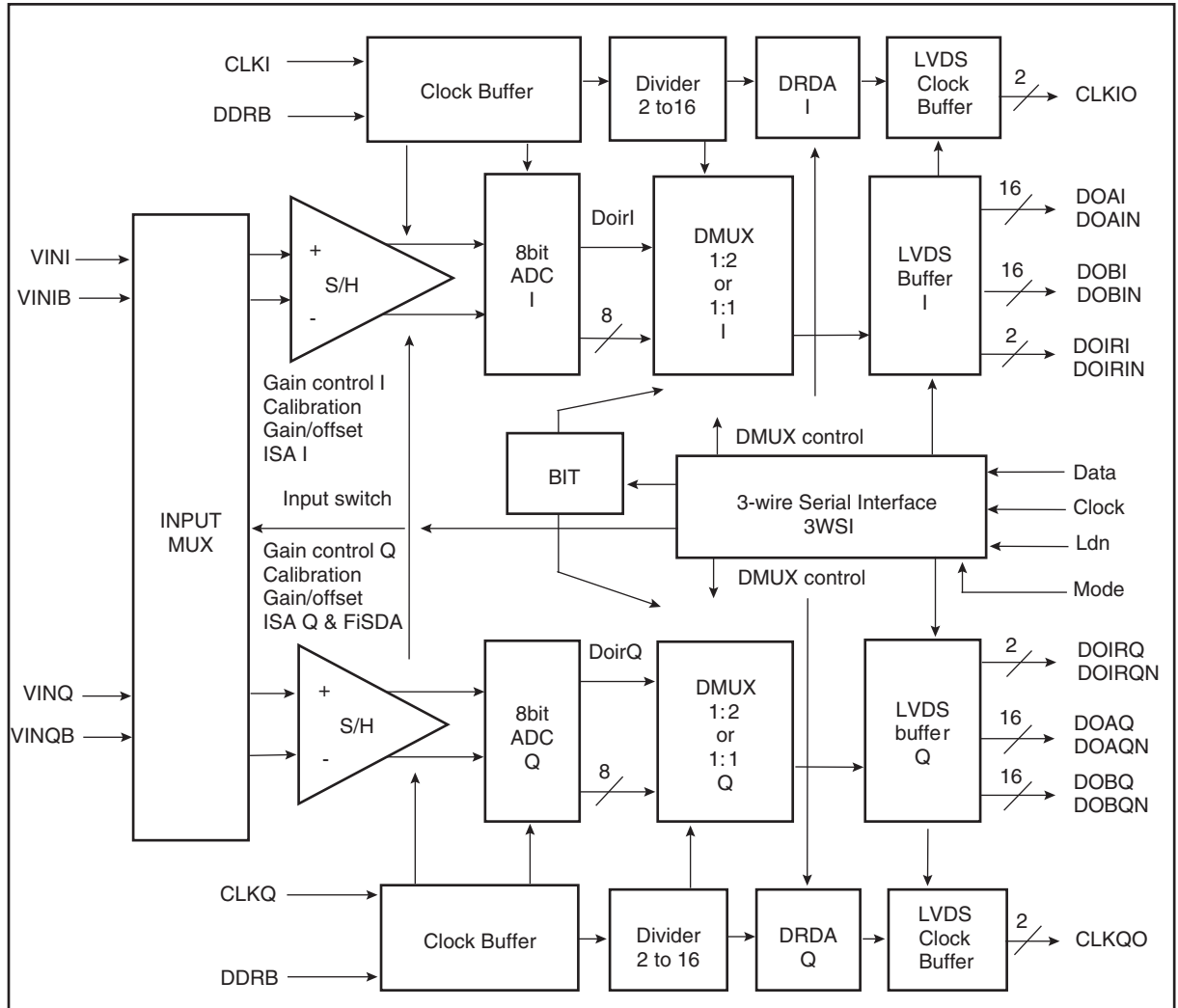
A 3-wire serial interface (3-bit address and 16-bit data) is included to provide several adjustments:

- Analog input range adjustment ( $\pm 1.5$  dB) with 8-bit data control using a 3-wire bus interface (steps of 0.011 dB)
- Analog input switch: both ADCs can convert the same analog input signal I or Q
- Gray or binary encoder output. Output format: DMUX 1:1 or 1:2 with control of the output frequency on the data ready output signal
- Partial or full standby on channel I or channel Q
- Clock selection:
  - Two independent clocks: CLKI and CLKQ
  - One master clock (CLKI) with the same phase for channel I and channel Q
  - One master clock but with two phases (CLKI for channel I and CLKIB for channel Q)
- ISA: Internal Settling Adjustment on channel I and channel Q
- FiSDA: Fine Sampling Delay Adjustment on channel Q
- Adjustable Data Ready Output Delay on both channels
- Test mode: decimation mode (by 16), Built-in Test

A calibration phase is provided to set the two DC offsets of channel I and channel Q close to code 127.5 and calibrate the two gains. The offset and gain error can also be set externally via the 3-wire serial interface.

The AT84AD004B operates in fully differential mode from the analog inputs up to the digital outputs. The AT84AD004B features a full-power input bandwidth of 1 GHz.

**Figure 5-1.** Simplified Block Diagram



## 6. Typical Applications

Figure 6-1. Satellite Receiver Application

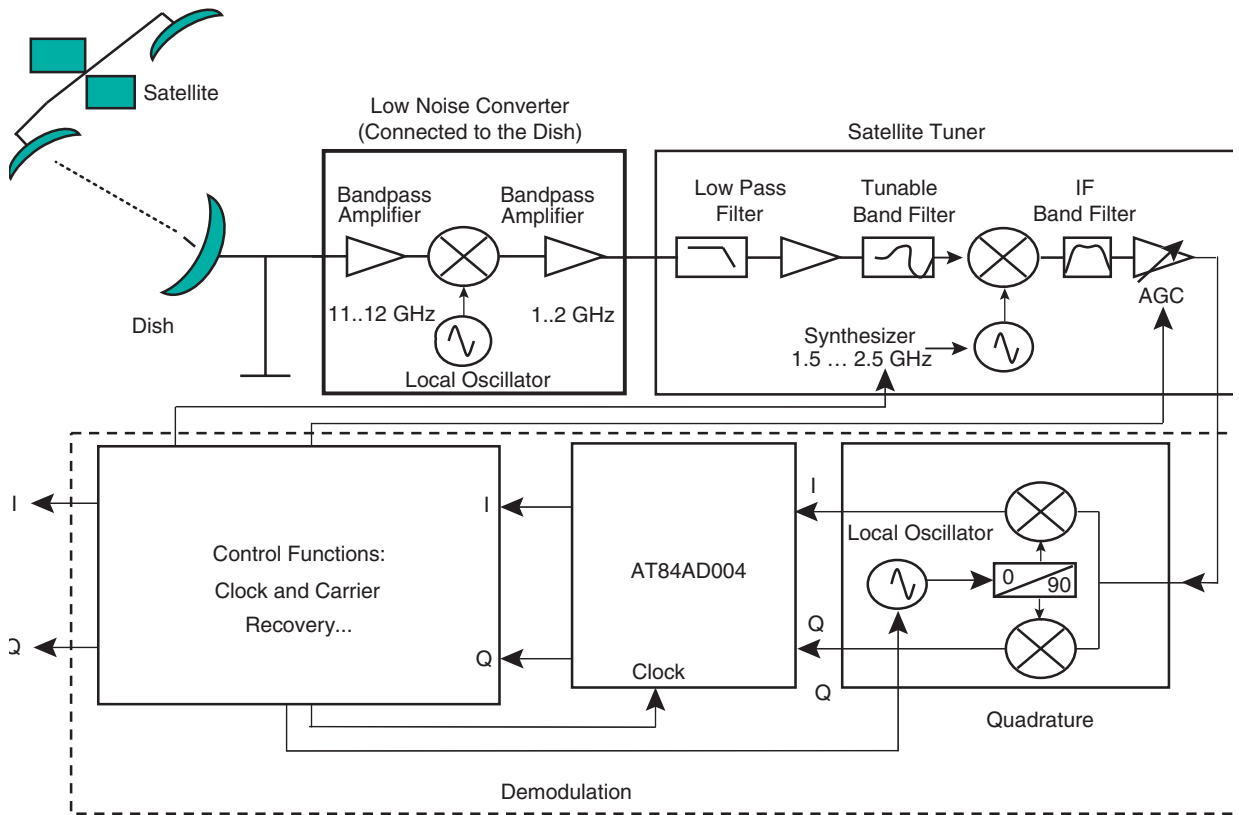
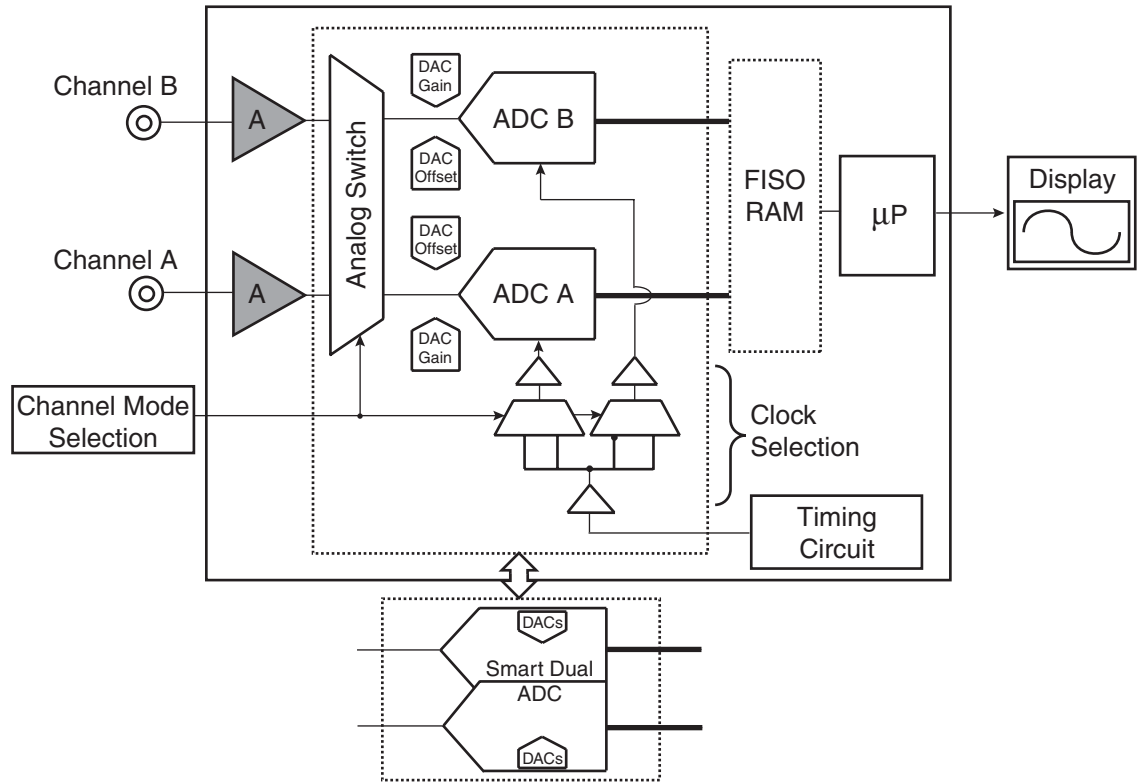


Figure 6-2. Dual Channel Digital Oscilloscope Application



### 6.1 Absolute Maximum Ratings

Table 6-1. Absolute Maximum Ratings

| Parameter   | Symbol   | Value                   | Unit |
|---|--|-------------------------|------|
| Analog positive supply voltage                      | $V_{CCA}$  | 3.6                     | V    |
| Digital positive supply voltage                     | $V_{CCD}$  | 3.6                     | V    |
| Output supply voltage                               | $V_{CCO}$  | 3.6                     | V    |
| Maximum difference between $V_{CCA}$ and $V_{CCD}$  | $V_{CCA}$ to $V_{CCD}$                             | $\pm 0.8$               | V    |
| Minimum $V_{CCO}$                                   | $V_{CCO}$  | 1.6                     | V    |
| Analog input voltage                                | $V_{INI}$ or $V_{INIB}$<br>$V_{INQ}$ or $V_{INQB}$ | 1/-1                    | V    |
| Digital input voltage                               | $V_D$  | -0.3 to $V_{CCD} + 0.3$ | V    |
| Clock input voltage                                 | $V_{CLK}$ or $V_{CLKB}$                            | -0.3 to $V_{CCD} + 0.3$ | V    |
| Maximum difference between $V_{CLK}$ and $V_{CLKB}$ | $V_{CLK} - V_{CLKB}$                               | -2 to 2                 | V    |
| Maximum junction temperature                        | $T_J$  | 125                     | °C   |
| Storage temperature                                 | $T_{stg}$  | -65 to 150              | °C   |
| Lead temperature (soldering 10s)                    | $T_{leads}$  | 300                     | °C   |

Note: Absolute maximum ratings are limiting values (referenced to GND = 0V), to be applied individually, while other parameters are within specified operating conditions. Long exposure to maximum ratings may affect device reliability.

## 6.2 Recommended Conditions of Use

**Table 6-2.** Recommended Conditions of Use

| Parameter   | Symbol  | Comments                             | Recommended Value                          | Unit |
|---|---|--------------------------------------|--|------|
| Analog supply voltage   | $V_{CCA}$                                       |                                      | 3.3  | V    |
| Digital supply voltage  | $V_{CCD}$                                       |                                      | 3.3  | V    |
| Output supply voltage   | $V_{CCO}$                                       |                                      | 2.25                                       | V    |
| Differential analog input voltage (full-scale)  | $V_{INI} - V_{INIB}$ or<br>$V_{INQ} - V_{INQB}$ |                                      | 500  | mVpp |
| Differential clock input level  | $V_{inclk}$                                     |                                      | 600  | mVpp |
| Internal Settling Adjustment (ISA) with a 3-wire serial interface for channel I and channel Q | ISA   |                                      | 0  | ps   |
| Operating temperature range   | $T_{Ambient}$                                   | Commercial grade<br>Industrial grade | $0 < T_{amb} < 70$<br>$-40 < T_{amb} < 85$ | °C   |

## 7. Electrical Operating Characteristics

Unless otherwise specified:

- $V_{CCA} = 3.3V$ ;  $V_{CCD} = 3.3V$ ;  $V_{CCO} = 2.25V$
- $V_{INI} - V_{INIB}$  or  $V_{INQ} - V_{INQB} = 500$  mVpp full-scale differential input
- LVDS digital outputs (100Ω)
- $T_{amb}$  (typical) = 25°C
- Full temperature range:  $0^{\circ}C < T_{amb} < 70^{\circ}C$  (commercial grade)

**Table 7-1.** Electrical Operating Characteristics in Nominal Conditions

| Parameter                                      | Symbol    | Min  | Typ  | Max  | Unit |
|--|-----------|------|------|------|------|
| <b>Resolution</b>                              |           |      | 8    |      | Bits |
| <b>Power Requirements</b>                      |           |      |      |      |      |
| Positive supply voltage                        |           |      |      |      |      |
| - Analog                                       | $V_{CCA}$ | 3.15 | 3.3  | 3.45 | V    |
| - Digital                                      | $V_{CCD}$ | 3.15 | 3.3  | 3.45 | V    |
| Output digital (LVDS) and serial interface     | $V_{CCO}$ | 2.0  | 2.25 | 2.5  | V    |
| Supply current (typical conditions)            |           |      |      |      |      |
| - Analog                                       | $I_{CCA}$ |      | 150  | 180  | mA   |
| - Digital                                      | $I_{CCD}$ |      | 230  | 275  | mA   |
| - Output                                       | $I_{CCO}$ |      | 100  | 120  | mA   |
| Supply current (1:2 DMUX mode)                 |           |      |      |      |      |
| - Analog                                       | $I_{CCA}$ |      | 150  | 180  | mA   |
| - Digital                                      | $I_{CCD}$ |      | 260  | 310  | mA   |
| - Output                                       | $I_{CCO}$ |      | 175  | 210  | mA   |
| Supply current (2 input clocks, 1:2 DMUX mode) |           |      |      |      |      |
| - Analog                                       | $I_{CCA}$ |      | 150  | 180  | mA   |
| - Digital                                      | $I_{CCD}$ |      | 290  | 350  | mA   |
| - Output                                       | $I_{CCO}$ |      | 180  | 215  | mA   |

**Table 7-1.** Electrical Operating Characteristics in Nominal Conditions (Continued)

| Parameter   | Symbol   | Min           | Typ  | Max  | Unit |
|---|--|---------------|------|------|------|
| Supply current<br>(1 channel only, 1:1 DMUX mode)   |  |               |      |      |      |
| - Analog  | $I_{CCA}$  |               | 80   | 95   | mA   |
| - Digital   | $I_{CCD}$  |               | 160  | 190  | mA   |
| - Output  | $I_{CCO}$  |               | 55   | 65   | mA   |
| Supply current<br>(1 channel only, 1:2 DMUX mode)   |  |               |      |      |      |
| - Analog  | $I_{CCA}$  |               | 80   | 95   | mA   |
| - Digital   | $I_{CCD}$  |               | 170  | 205  | mA   |
| - Output  | $I_{CCO}$  |               | 90   | 110  | mA   |
| Supply current (full standby mode)  |  |               |      |      |      |
| - Analog  | $I_{CCA}$  |               | 12   | 20   | mA   |
| - Digital   | $I_{CCD}$  |               | 24   | 39   | mA   |
| - Output  | $I_{CCO}$  |               | 3    | 7    | mA   |
| Nominal dissipation<br>(1 clock, 1:1 DMUX mode, 2 channels)   | $P_D$  |               | 1.4  | 1.7  | W    |
| Nominal dissipation (full standby mode)   | stbpd  |               | 120  |      | mW   |
| <b>Analog Inputs</b>  |  |               |      |      |      |
| Full-scale differential analog input voltage to obtain full-scale with no gain adjust (mode 0)                  | $V_{INI} - V_{IniB}$<br>or<br>$V_{INQ} - V_{INQB}$ | 450           | 500  | 550  | mV   |
| Analog input common mode  |  |               | 0    |      | V    |
| Analog input capacitance I and Q  | $C_{IN}$   |               |      | 2    | pF   |
| Full power input bandwidth (–3 dB)  | FPBW   |               | 1.0  |      | GHz  |
| Gain flatness (–0.5 dB)   |  |               | 400  |      | MHz  |
| <b>Clock Input</b>  |  |               |      |      |      |
| Logic compatibility for clock inputs and DDRB Reset (pins 124,125,126,127,128,129)                              |  | PECL/ECL/LVDS |      |      |      |
| PECL/LVDS clock inputs and DDRB input voltages ( $V_{CLKI/IN}$ or $V_{CLKQ/QN}$ )<br>Differential logical level | $V_{IL} - V_{IH}$                                  |               | 600  |      | mV   |
| Clock input and DDRB input power level  |  | –9            | 0    | 6    | dBm  |
| Clock input capacitance   |  |               | 2    |      | pF   |
| <b>Digital Outputs (including DOIRI, DOIRIN, DOIRQ and DOIRQN signals)</b>                                      |  |               |      |      |      |
| Logic compatibility for digital outputs (depending on the value of $V_{CCO}$ )                                  |  | LVDS          |      |      |      |
| Differential output voltage swings (assuming $V_{CCO} = 2.25V$ )  | $V_{OD}$   | 220           | 270  | 350  | mV   |
| Output levels (assuming $V_{CCO} = 2.25V$ )<br>100Ω differentially terminated                                   |  |               |      |      |      |
| Logic 0 voltage   | $V_{OL}$   | 1.0           | 1.1  | 1.2  | V    |
| Logic 1 voltage   | $V_{OH}$   | 1.25          | 1.35 | 1.48 | V    |

**Table 7-1.** Electrical Operating Characteristics in Nominal Conditions (Continued)

| Parameter   | Symbol   | Min             | Typ             | Max             | Unit            |
|---|----------|-----------------|-----------------|-----------------|-----------------|
| Output offset voltage (assuming $V_{CCO} = 2.25V$ )<br>100 $\Omega$ differentially terminated | $V_{OS}$ | 1125            | 1250            | 1340            | mV              |
| Output impedance  | $R_O$    |                 | 50              |                 | $\Omega$        |
| Output current (shorted output)   |          |                 |                 | 12              | mA              |
| Output current (grounded output)  |          |                 | 30              |                 | mA              |
| Output level drift with temperature   |          |                 | 1.3             |                 | mV/ $^{\circ}C$ |
| Digital Input (Serial Interface)  |          |                 |                 |                 |                 |
| Maximum clock frequency (input clk)   | Fclk     |                 |                 | 50              | MHz             |
| Input logical level 0 (clk, mode, data, ldn)  |          | -0.4            | 0               | 0.4             | V               |
| Input logical level 1 (clk, mode, data, ldn)  |          | $V_{CCO} - 0.4$ | $V_{CCO} - 0.4$ | $V_{CCO} + 0.4$ | V               |
| Output logical level 0 (cal)  |          | -0.4            | 0               | 0.4             | V               |
| Output logical level 1 (cal)  |          | $V_{CCO} - 0.4$ | $V_{CCO}$       | $V_{CCO} + 0.4$ | V               |
| Maximum output load (cal)   |          |                 |                 | 15              | pF              |

Note: The gain setting is 0 dB, one clock input, no standby mode [full power mode], 1:1 DMUX, calibration off.

**Table 7-2.** Electrical Operating Characteristics

| Parameter   | Symbol | Min   | Typ        | Max | Unit             |
|---|--------|---|------------|-----|------------------|
| DC Accuracy   |        |   |            |     |                  |
| No missing code   |        | Guaranteed over specified temperature range |            |     |                  |
| Differential non-linearity  | DNL    |   | 0.25       | 0.6 | LSB              |
| Integral non-linearity  | INL    |   | 0.5        | 1   | LSB              |
| Gain error (single channel I or Q) with calibration   |        | -2  | 0          | 2   | %                |
| Input offset matching (single channel I or Q) with calibration  |        | -2  | 0          | 2   | LSB              |
| Gain error drift against temperature  |        |   | 0.062      |     | LSB/ $^{\circ}C$ |
| Gain error drift against $V_{CCA}$  |        |   | 0.064      |     | LSB/mV           |
| Mean output offset code with calibration  |        | 126   | 127.5      | 129 | LSB              |
| Transient Performance   |        |   |            |     |                  |
| Bit Error Rate<br>Fs = 500 Msp<br>Fin = 250 MHz   | BER    |   | $10^{-18}$ |     | Error/<br>sample |
| ADC settling time channel I or Q<br>(between 10% – 90% of output response)<br>$V_{ini} - V_{iniB} = 500$ mVpp | TS     |   | 170        |     | ps               |

Note: The gain setting is 0 dB, two clock inputs, no standby mode [full power mode], 1:2 DMUX, calibration on.



**Table 7-3. AC Performance**

| Parameter   | Symbol         | Min  | Typ | Max | Unit |
|---|----------------|------|-----|-----|------|
| AC Performance  |                |      |     |     |      |
| Signal-to-noise Ratio   |                |      |     |     |      |
| Fs = 500 Msps Fin = 20 MHz  | SNR            | 44   | 46  |     | dBc  |
| Fs = 500 Msps Fin = 250 MHz   |                | 43   | 45  |     | dBc  |
| Fs = 500 Msps Fin = 500 MHz   |                | 42   | 44  |     | dBc  |
| Effective Number of Bits  |                |      |     |     |      |
| Fs = 500 Msps Fin = 20 MHz  | ENOB           | 7    | 7.4 |     | Bits |
| Fs = 500 Msps Fin = 250 MHz   |                | 6.9  | 7.2 |     | Bits |
| Fs = 500 Msps Fin = 500 MHz   |                | 6.7  | 7.0 |     | Bits |
| Total Harmonic Distortion (First 9 Harmonics)   |                |      |     |     |      |
| Fs = 500 Msps Fin = 20 MHz  | ITHDI          | 48   | 55  |     | dBc  |
| Fs = 500 Msps Fin = 250 MHz   |                | 47   | 53  |     | dBc  |
| Fs = 500 Msps Fin = 500 MHz   |                | 47   | 53  |     | dBc  |
| Spurious Free Dynamic Range   |                |      |     |     |      |
| Fs = 500 Msps Fin = 20 MHz  | ISFDRI         | 50   | 57  |     | dBc  |
| Fs = 500 Msps Fin = 250 MHz   |                | 49   | 56  |     | dBc  |
| Fs = 500 Msps Fin = 500 MHz   |                | 49   | 56  |     | dBc  |
| Two-tone Inter-modulation Distortion (Single Channel)   |                |      |     |     |      |
| $F_{IN1} = 249 \text{ MHz}$ , $F_{IN2} = 251 \text{ MHz}$ at Fs = 500 Msps  | IMD            |      | -54 |     | dBc  |
| Phase matching using auto-calibration and FiSDA in interleaved mode (channel I and Q)<br>Fin = 250 MHz<br>Fs = 500 Msps | d <sub>φ</sub> | -1.4 | 0   | 1.4 | °    |
| Crosstalk channel I versus channel Q<br>Fin = 250 MHz, Fs = 500 Msps <sup>(2)</sup>                                     | Cr             |      | -55 |     | dB   |

- Notes: 1. Differential input [-1 dBFS analog input level], gain setting is 0 dB, two input clock signals, no standby mode, 1:1 DMUX, ISA = 0 ps.  
2. Measured on the AT84AD004BTD-EB Evaluation Board.

**Table 7-4.** AC Performances Over Full Industrial Temperature Range ( $-40^{\circ}\text{C} < T_{\text{amb}} < 85^{\circ}\text{C}$ )

| Parameter                                     | Symbol | Min | Typ | Max | Unit |
|---|--------|-----|-----|-----|------|
| AC Performance                                |        |     |     |     |      |
| Signal-to-noise Ratio                         |        |     |     |     |      |
| Fs = 500 Msps Fin = 500 MHz                   |        | 41  | 44  |     | dBc  |
| Effective Number of Bits                      |        |     |     |     |      |
| Fs = 500 Msps Fin = 500 MHz                   |        | 6.5 | 7.0 |     | Bits |
| Total Harmonic Distortion (First 9 Harmonics) |        |     |     |     |      |
| Fs = 500 Msps Fin = 500 MHz                   |        | 43  | 53  |     | dBc  |
| Spurious Free Dynamic Range                   |        |     |     |     |      |
| Fs = 500 Msps Fin = 500 MHz                   |        | 45  | 56  |     | dBc  |

**Table 7-5.** AC Performances in Interleaved Mode

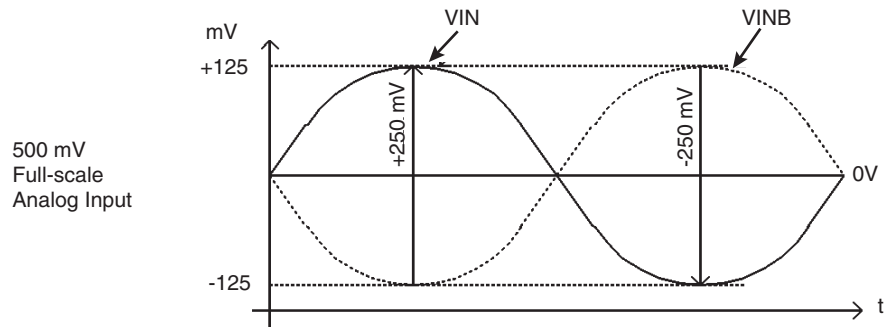
| Parameter  | Symbol           | Min | Typ  | Max | Unit |
|--|------------------|-----|------|-----|------|
| Interleaved Mode   |                  |     |      |     |      |
| Maximum equivalent clock frequency $F_{\text{int}} = 2 \times F_{\text{s}}$<br>Where $F_{\text{s}}$ = external clock frequency | $F_{\text{int}}$ | 1   |      |     | Gsps |
| Minimum clock frequency  | $F_{\text{int}}$ |     | 20   |     | Msps |
| Differential non-linearity in interleaved mode   | intDNL           |     | 0.25 |     | LSB  |
| Integral non-linearity in interleaved mode   | intINL           |     | 0.5  |     | LSB  |
| <b>Signal-to-noise Ratio in interleaved Mode</b>   |                  |     |      |     |      |
| Fint = 1 Gsps Fin = 20 MHz   | iSNR             |     | 45   |     | dBc  |
| Fint = 1 Gsps Fin = 250 MHz  |                  |     | 44   |     | dBc  |
| <b>Effective Number of Bits in interleaved Mode</b>  |                  |     |      |     |      |
| Fint = 1 Gsps Fin = 20 MHz   | iENOB            |     | 7.3  |     | Bits |
| Fint = 1 Gsps Fin = 250 MHz  |                  |     | 7.1  |     | Bits |
| Total Harmonic Distortion in interleaved Mode  |                  |     |      |     |      |
| Fint = 1 Gsps Fin = 20 MHz   | liTHDI           |     | 54   |     | dBc  |
| Fint = 1 Gsps Fin = 250 MHz  |                  |     | 53   |     | dBc  |
| Spurious Free Dynamic Range in interleaved Mode  |                  |     |      |     |      |
| Fint = 1 Gsps Fin = 20 MHz   | liSFDRI          |     | 56   |     | dBc  |
| Fint = 1 Gsps Fin = 250 MHz  |                  |     | 55   |     | dBc  |
| Two-tone Inter-modulation Distortion (Single Channel) in interleaved Mode  |                  |     |      |     |      |
| $F_{\text{IN1}} = 249\text{ MHz}$ , $F_{\text{IN2}} = 251\text{ MHz}$ at $F_{\text{int}} = 1\text{ Gsps}$                      | iIMD             |     | -54  |     | dBc  |

Note: One analog input on both cores, clock I samples the analog input on the rising and falling edges. The calibration phase is necessary. The gain setting is 0 dB, one input clock I, no standby mode, 1:1 DMUX, FiSDA adjustment.

Table 7-6. Switching Performances

| Parameter   | Symbol           | Min  | Typ                | Max | Unit         |
|---|------------------|--|--------------------|-----|--------------|
| Switching Performance and Characteristics – See “Timing Diagrams” on page 12. |                  |  |                    |     |              |
| Maximum operating clock frequency   | $F_S$            | 500  |                    |     | MspS         |
| Minimum clock frequency (no transparent mode)                                 | $F_S$            |  | 10                 |     | MspS         |
| Minimum clock frequency (with transparent mode)                               |                  |  | 1                  |     | KspS         |
| Minimum clock pulse width [high]<br>(No transparent mode)                     | TC1              | 0.4  | 1                  | 50  | ns           |
| Minimum clock pulse width [low]<br>(No transparent mode)                      | TC2              | 0.4  | 1                  | 50  | ns           |
| Aperture delay: nominal mode with ISA & FiSDA                                 | TA               |  | 1                  |     | ns           |
| Aperture uncertainty  | Jitter           |  | 0.4                |     | ps (rms)     |
| Data output delay between input clock and data                                | TDO              |  | 3.8                |     | ns           |
| Data Ready Output Delay   | TDR              |  | 3                  |     | ns           |
| Data Ready Reset to Data Ready  | TRDR             |  | 2                  |     | ns           |
| Data Output Delay with Data Ready   | TD2              |  | $1/F_S + T_{drda}$ |     | ps           |
| Data Ready (CLKO) Delay Adjust (140 ps steps)                                 | $T_{drda}$ range |  | –560 to 420        |     | ps           |
| Output skew   |                  | 50   |                    | 100 | ps           |
| Output rise/fall time for DATA (20% – 80%)                                    | TR/TF            | 300  | 350                | 500 | ps           |
| Output rise/fall time for DATA READY (20% – 80%)                              | TR/TF            | 300  | 350                | 500 | ps           |
| Data pipeline delay (nominal mode)  | TPD              | 3 (port B)<br>3.5 (port A, 1:1 DMUX mode)<br>4 (port A, 1:2 DMUX mode)   |                    |     | Clock cycles |
| Data pipeline delay (nominal mode) in S/H transparent mode                    |                  | 2.5 (port B)<br>3 (port A, 1:1 DMUX mode)<br>3.5 (port A, 1:2 DMUX mode) |                    |     |              |
| DDRb recommended pulse width  |                  | 1  |                    |     | ns           |

**Figure 7-1.** Differential Inputs Voltage Span (Full-scale)

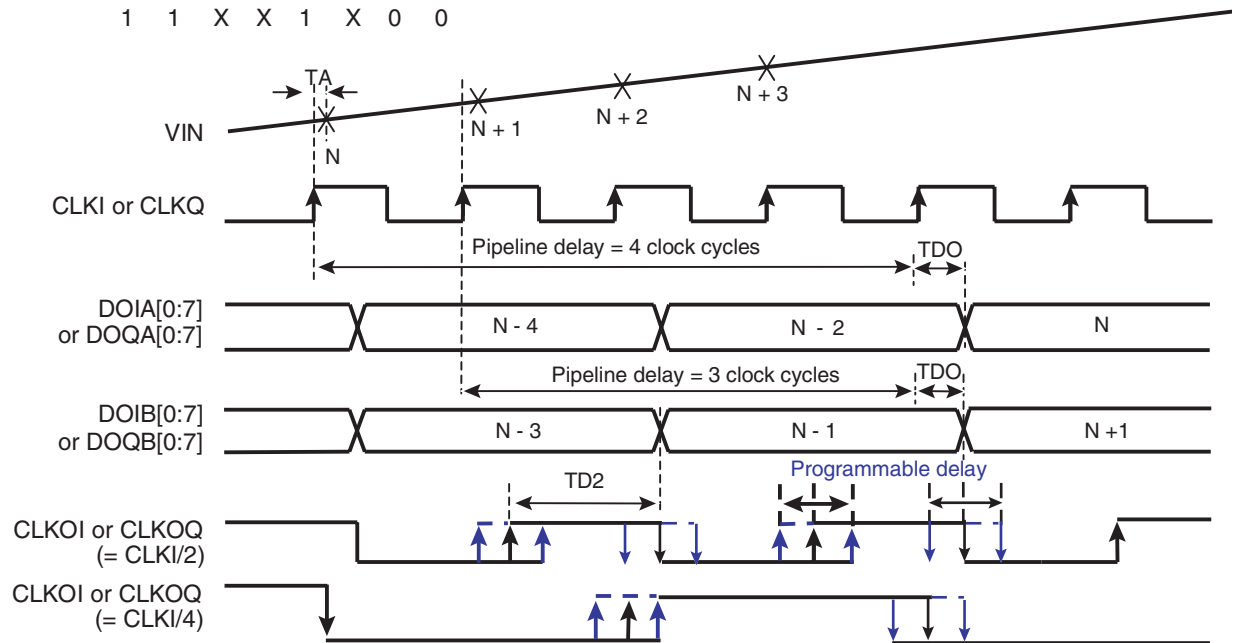


The analog input full-scale range is 0.5V peak-to-peak ( $V_{pp}$ ), or  $-2$  dBm into the  $50\Omega$  ( $100\Omega$  differential) termination resistor. In differential mode input configuration, which means 0.25V on each input, or  $\pm 125$  mV around common mode voltage.

## 7.1 Timing Diagrams

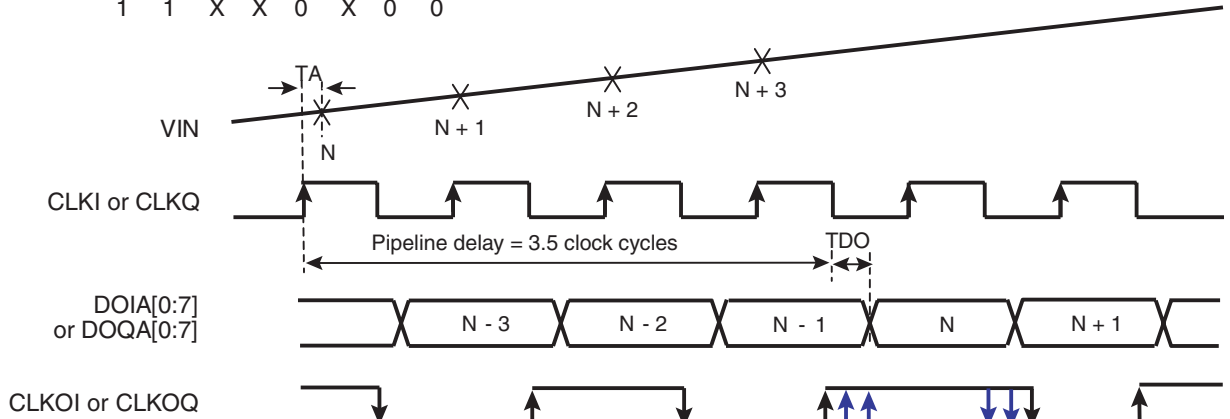
**Figure 7-2.** Timing Diagram, ADC I or ADC Q, 1:2 DMUX Mode, Clock I for ADC I, Clock Q for ADC Q

Address: D7 D6 D5 D4 D3 D2 D1 D0  
 1 1 X X 1 X 0 0



**Figure 7-3.** 1:1 DMUX Mode, Clock I = ADC I, Clock Q = ADC Q

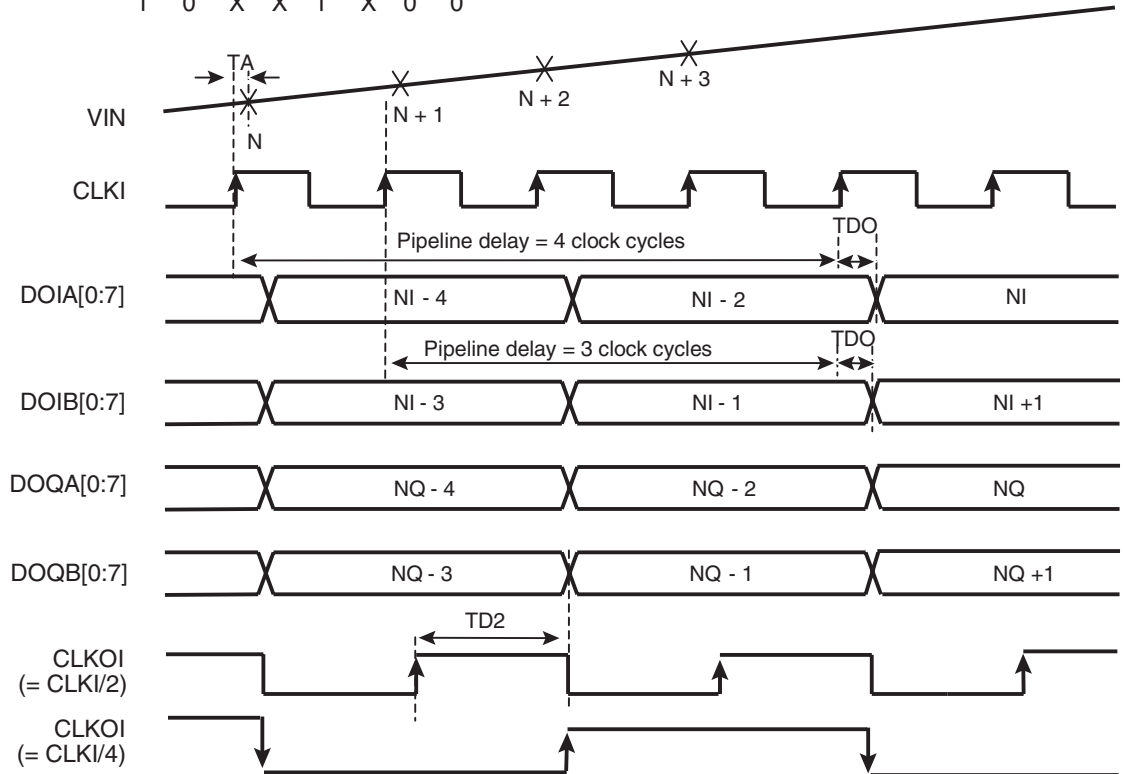
Address: D7 D6 D5 D4 D3 D2 D1 D0  
 1 1 X X 0 X 0 0



DOIB[0:7] and DOQB[0:7] are high impedance

**Figure 7-4.** 1:2 DMUX Mode, Clock I = ADC I, Clock I = ADC Q

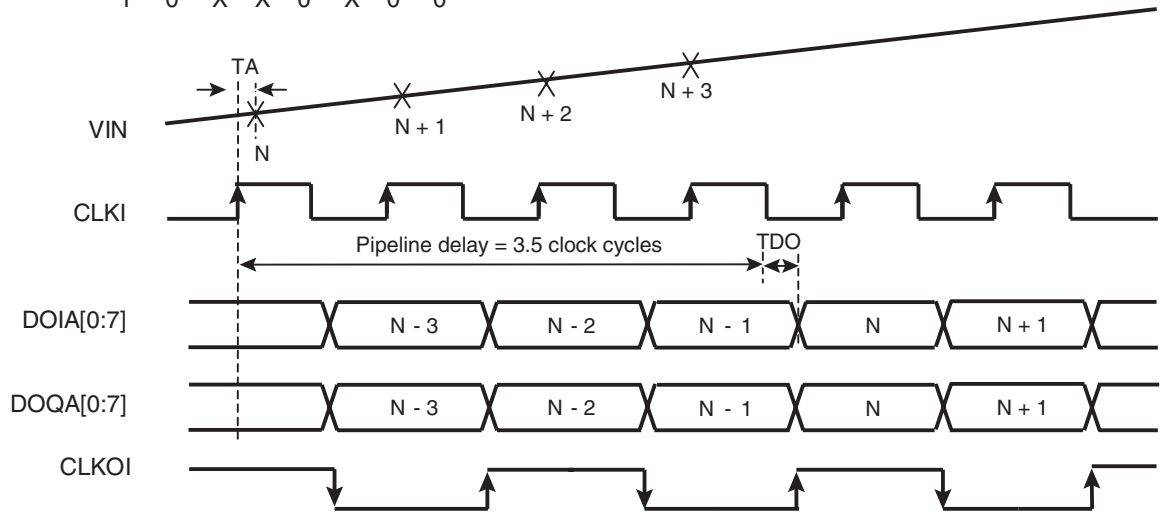
Address: D7 D6 D5 D4 D3 D2 D1 D0  
 1 0 X X 1 X 0 0



CLKOQ is high impedance

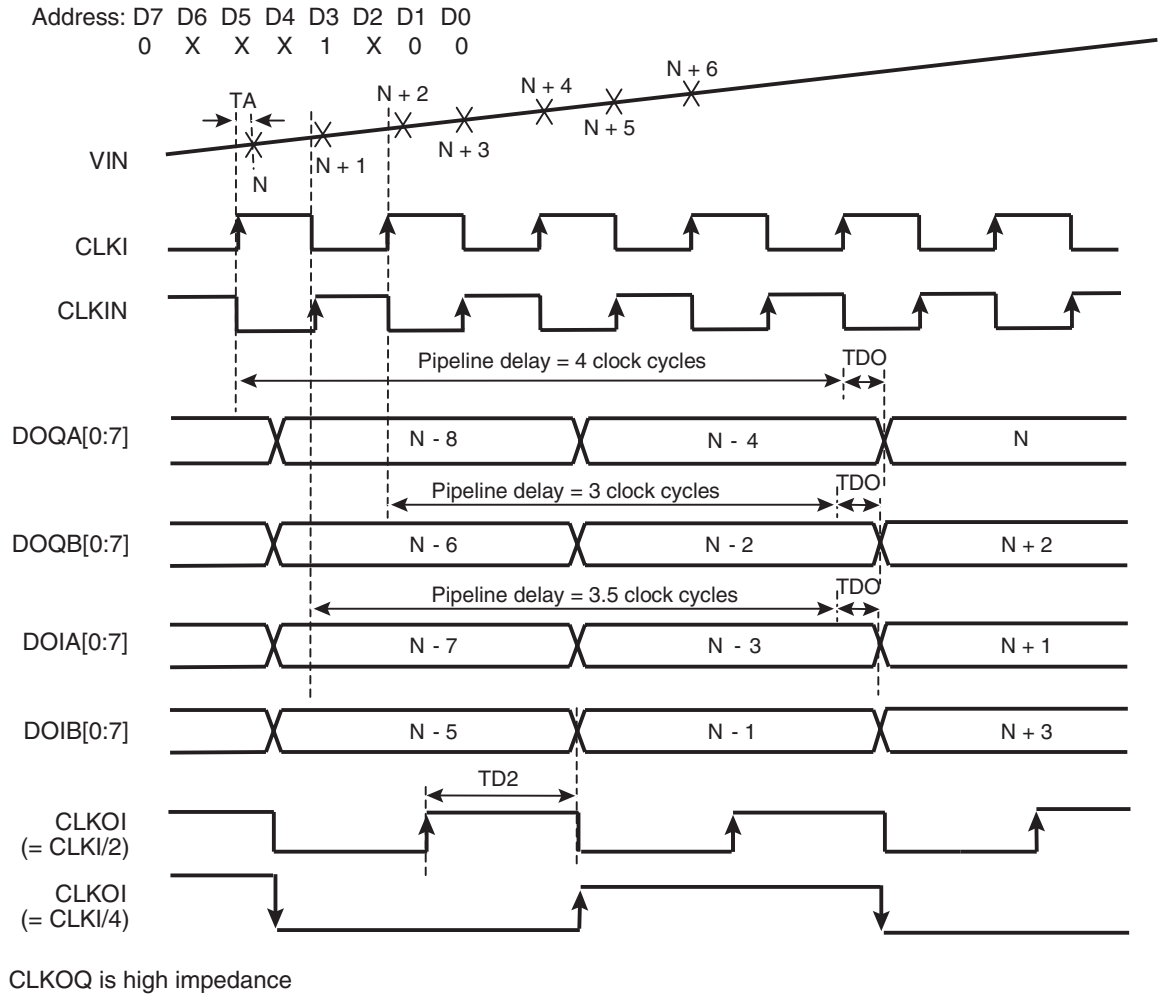
**Figure 7-5.** 1:1 DMUX Mode, Clock I = ADC I, Clock I = ADC Q

Address: D7 D6 D5 D4 D3 D2 D1 D0  
 1 0 X X 0 X 0 0

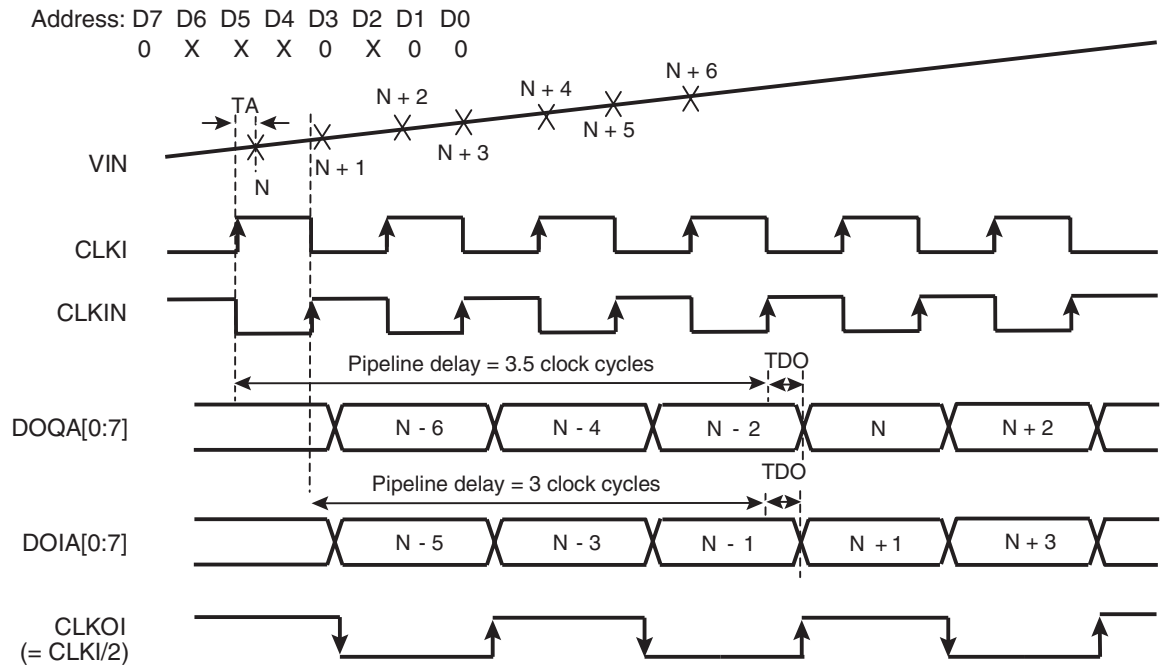


DOIB[0:7] and DOQB[0:7] are high impedance  
 CLKOQ is high impedance

**Figure 7-6.** 1:2 DMUX Mode, Clock I = ADC I, Clock IN = ADC Q

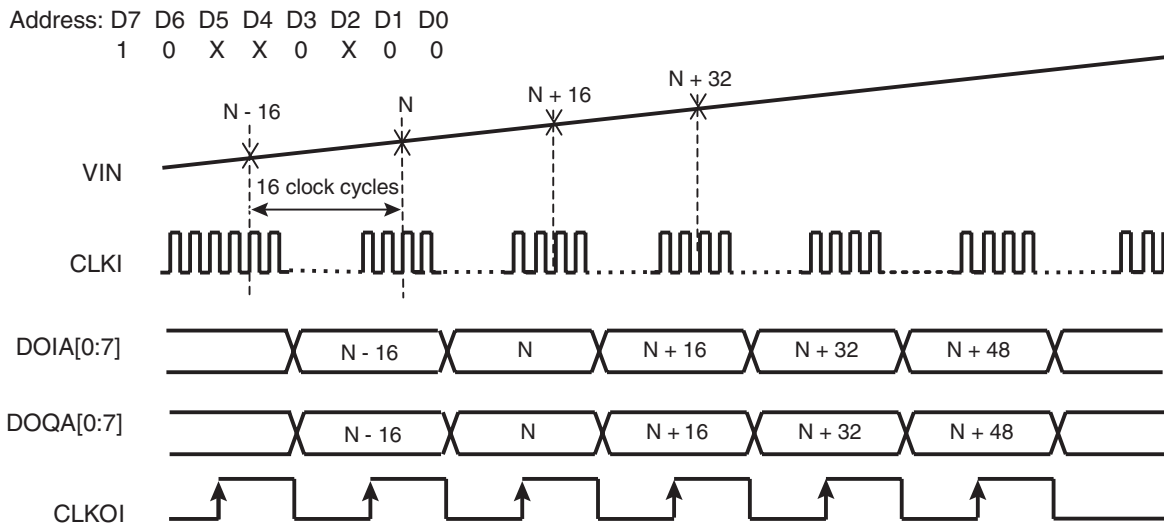


**Figure 7-7.** 1:1 DMUX Mode, Clock I = ADC I, Clock IN = ADC Q



DOIB[0:7] and DOQB[0:7] are high impedance  
 CLKOQ is high impedance

**Figure 7-8.** 1:1 DMUX Mode, Decimation Mode Test (1:16 Factor)



DOIB[0:7] and DOQB[0:7] are high impedance  
 CLKOQ is high impedance

Note: Frequency(CLKOI) = Frequency(Data) = Frequency(CLKI)/16.



Figure 7-9. Data Ready Reset

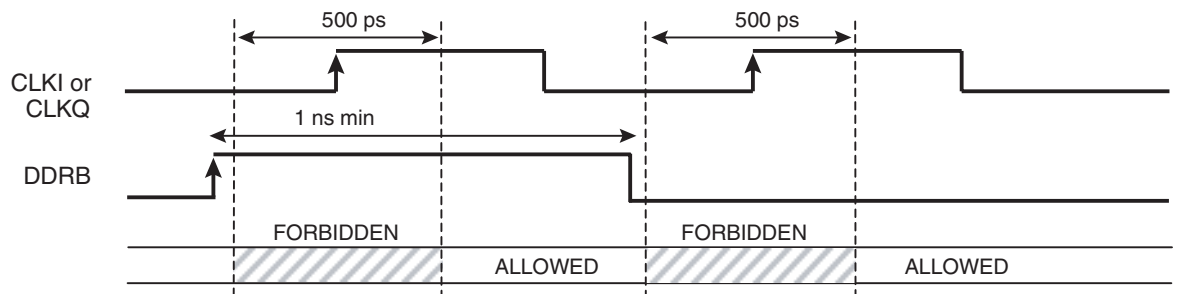
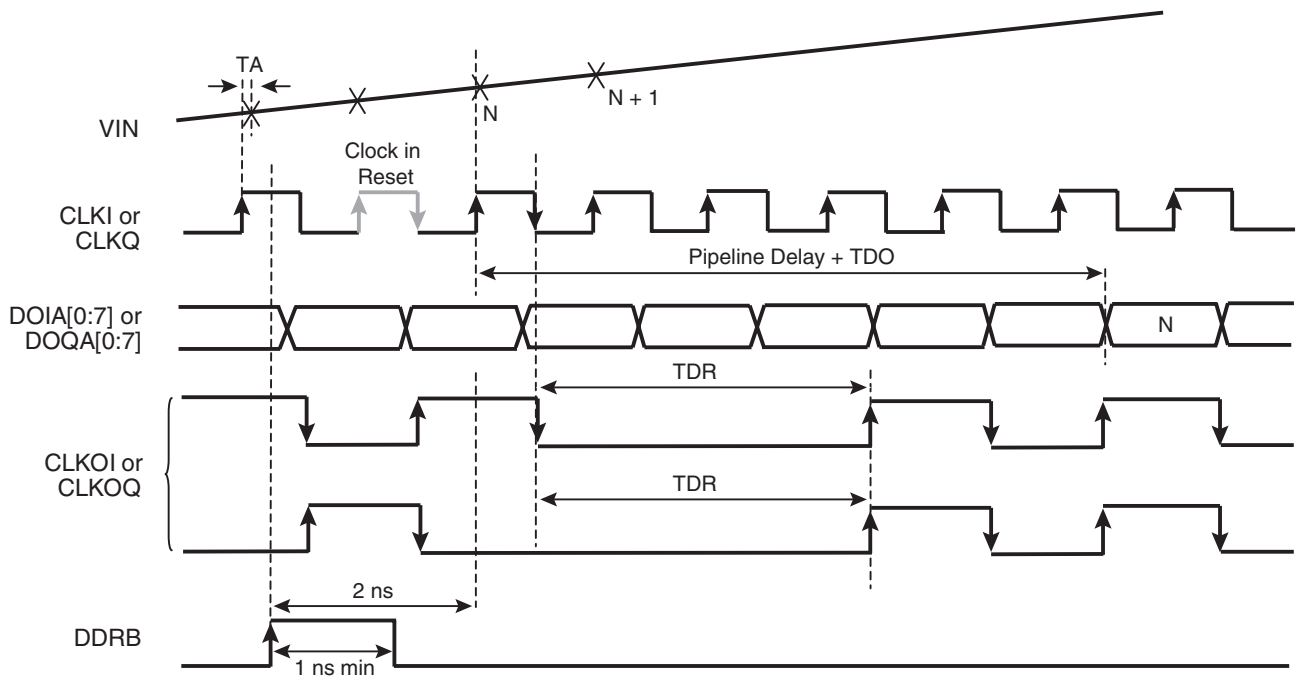
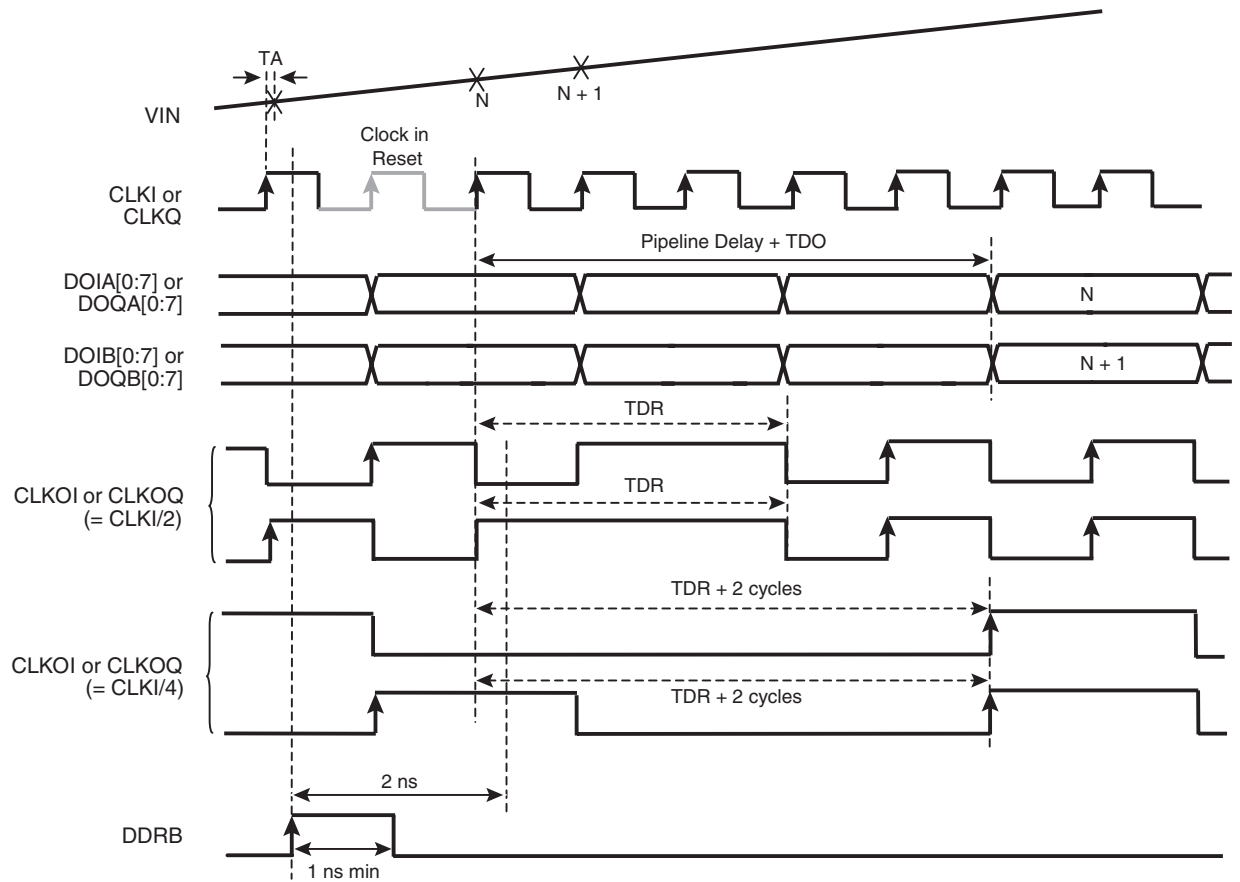


Figure 7-10. Data Ready Reset 1:1 DMUX Mode



Note: The Data Ready Reset is taken into account only 2 ns after it is asserted. The output clock first completes its cycle (if the reset occurs when it is high, it goes low only when its half cycle is complete; if the reset occurs when it is low, it remains low) and then only, remains in reset state (frozen to a low level in 1:1 DMUX mode). The next falling edge of the input clock after reset makes the output clock return to normal mode (after TDR).

Figure 7-11. Data Ready Reset 1:2 DMUX Mode

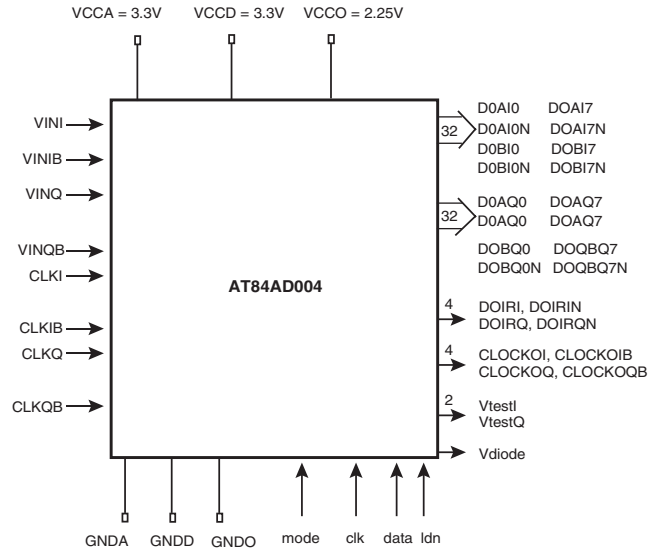


- Notes:
1. In 1:2 DMUX, Fs/2 mode:  
The Data Ready Reset is taken into account only 2 ns after it is asserted. The output clock first completes its cycle (if the reset occurs when it is low, it goes high only when its half cycle is complete; if the reset occurs when it is high, it remains high) and then only, remains in reset state (frozen to a high level in 1:2 DMUX Fs/2 mode). The next rising edge of the input clock after reset makes the output clock return to normal mode (after TDR).
  2. In 1:2 DMUX, Fs/4 mode:  
The Data Ready Reset is taken into account only 2 ns after it is asserted. The output clock first completes its cycle (if the reset occurs when it is high, it goes low only when its half cycle is complete; if the reset occurs when it is low, it remains low) and then only, remains in reset state (frozen to a low level in 1:2 DMUX Fs/4 mode). The next rising edge of the input clock after reset makes the output clock return to normal mode (after TDR).

7.2 Functions Description

Table 7-7. Description of Functions

| Name   | Function  |
|--|---|
| V <sub>CCA</sub>   | Positive analog power supply                                |
| V <sub>CDD</sub>   | Positive digital power supply                               |
| V <sub>CCO</sub>   | Positive output power supply                                |
| GNDA   | Analog ground   |
| GNDD   | Digital ground  |
| GNDO   | Output ground   |
| V <sub>INI</sub> , V <sub>INIB</sub>                                 | Differential analog inputs I                                |
| V <sub>INQ</sub> , V <sub>INQB</sub>                                 | Differential analog inputs Q                                |
| CLKOI, CLKOIN, CLKOQ, CLKOQN   | Differential output data ready I and Q                      |
| CLKI, CLKIN, CLKQ, CLKQN   | Differential clock inputs I and Q                           |
| DRRB, DRBPN  | Synchronous data ready reset I and Q                        |
| Mode   | Bit selection for 3-wire bus or nominal setting             |
| Clk  | Input clock for 3-wire bus interface                        |
| Data   | Input data for 3-wire bus                                   |
| Ldn  | Beginning and end of register line for 3-wire bus interface |
| <D0AI0:DOAI7> <D0AI0N:DOAI7N><br><D0BI0:DOBI7> <D0BI0N:DOBI7N>       | Differential output data port channel I                     |
| <D0AQ0:DOAQ7><br><D0AQ0N:DOAQ7N><br><D0BQ0:DOBQ7><br><D0BQ0N:DOBQ7N> | Differential output data port channel Q                     |
| DOIRI, DOIRIN DOIRQ, DOIRQN  | Differential output IN range data I and Q                   |
| VtestQ   | Test voltage output for ADC Q (to be left open)             |
| VtestI   | Test voltage output for ADC I (to be left open)             |
| Cal  | Output bit status internal calibration                      |
| Vdiode   | Test diode voltage for T <sub>j</sub> measurement           |



## 7.3 Digital Output Coding (Nominal Settings)

**Table 7-8.** Digital Output Coding (Nominal Setting)

| Differential Analog Input | Voltage Level                   | Digital Output I or Q (Binary Coding) | Out-of-range Bit |
|---------------------------|---------------------------------|---------------------------------------|------------------|
| > 250 mV                  | > Positive full-scale + 1/2 LSB | 1 1 1 1 1 1 1 1                       | 1                |
| 250 mV                    | Positive full-scale + 1/2 LSB   | 1 1 1 1 1 1 1 1                       | 0                |
| 248 mV                    | Positive full-scale – 1/2 LSB   | 1 1 1 1 1 1 1 0                       | 0                |
| 1 mV                      | Bipolar zero + 1/2 LSB          | 1 0 0 0 0 0 0 0                       | 0                |
| –1 mV                     | Bipolar zero – 1/2 LSB          | 0 1 1 1 1 1 1 1                       | 0                |
| –248 mV                   | Negative full-scale + 1/2 LSB   | 0 0 0 0 0 0 0 1                       | 0                |
| –250 mV                   | Negative full-scale – 1/2 LSB   | 0 0 0 0 0 0 0 0                       | 0                |
| < –250 mV                 | < Negative full-scale – 1/2 LSB | 0 0 0 0 0 0 0 0                       | 1                |

## 8. Pin Description

**Table 8-1.** AT84AD004B Pin Description

| Symbol  | Pin number  | Function  |
|---|---|---|
| GNDA, GNDD, GNDO  | 10, 12, 22, 24, 36, 38, 40, 42, 44, 46, 51, 54, 59, 61, 63, 65, 67, 69, 85, 87, 97, 99, 109, 111, 130, 142, 144 | Ground pins. To be connected to external ground plane   |
| V <sub>CCA</sub>  | 41, 43, 45, 60, 62, 64  | Analog positive supply: 3.3V typical  |
| V <sub>CCD</sub>  | 9, 21, 37, 39, 66, 68, 88, 100, 112, 123, 141   | 3.3V digital supply   |
| V <sub>CCO</sub>  | 11, 23, 86, 98, 110, 143  | 2.25V output and 3-wire serial interface supply   |
| V <sub>INI</sub>  | 57, 58  | In-phase (+) analog input signal of the sample & hold differential preamplifier channel I                     |
| V <sub>INIB</sub>   | 55, 56  | Inverted phase (–) of analog input signal (V <sub>INI</sub> )   |
| V <sub>INQ</sub>  | 47, 48  | In-phase (+) analog input signal of the sample & hold differential preamplifier channel Q                     |
| V <sub>INQB</sub>   | 49, 50  | Inverted phase (–) of analog input signal (V <sub>INQ</sub> )   |
| CLKI  | 124   | In-phase (+) clock input signal   |
| CLKIN   | 125   | Inverted phase (–) clock input signal (CLKI)  |
| CLKQ  | 129   | In-phase (+) clock input signal   |
| CLKQN   | 128   | Inverted phase (–) clock input signal (CLKQ)  |
| DDRB  | 126   | Synchronous data ready reset I and Q  |
| DDRBN   | 127   | Inverted phase (–) of input signal (DDRB)   |
| DOAI0, DOAI1, DOAI2, DOAI3, DOAI4, DOAI5, DOAI6, DOAI7          | 117, 113, 105, 101, 93, 89, 81, 77  | In-phase (+) digital outputs first phase demultiplexer (channel I) DOAI0 is the LSB. DOAI7 is the MSB         |
| DOAI0N, DOAI1N, DOAI2N, DOAI3N, DOAI4N, DOAI5N, DOAI6N, DOAI7N, | 118, 114, 106, 102, 94, 90, 82, 78  | Inverted phase (–) digital outputs first phase demultiplexer (channel I) DOAI0N is the LSB. DOAI7N is the MSB |
| DOBI0, DOBI1, DOBI2, DOBI3, DOBI4, DOBI5, DOBI6, DOBI7          | 119, 115, 107, 103, 95, 91, 83, 79  | In-phase (+) digital outputs second phase demultiplexer (channel I) DOBI0 is the LSB. DOBI7 is the MSB        |

**Table 8-1. AT84AD004B Pin Description (Continued)**

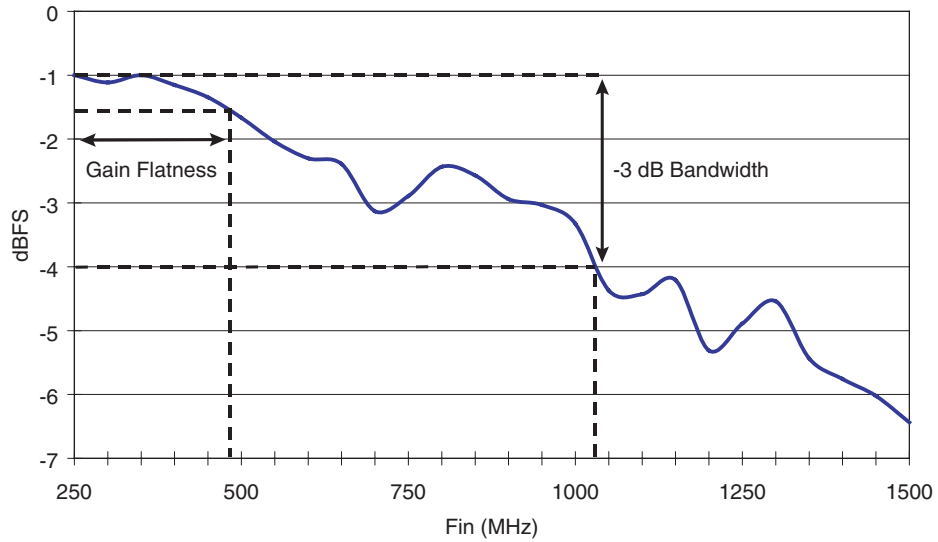
| Symbol   | Pin number                         | Function   |
|--|------------------------------------|--|
| DOBI0N, DOBI1N, DOBI2N, DOBI3N, DOBI4N, DOBI5N, DOBI6N, DOBI7N | 120, 116, 108, 104, 96, 92, 84, 80 | Inverted phase (–) digital outputs second phase demultiplexer (channel I) DOBI0N is the LSB. DOBI7N is the MSB                       |
| DOAQ0, DOAQ1, DOAQ2, DOAQ3, DOAQ4, DOAQ5, DOAQ6, DOAQ7         | 136, 140, 4, 8, 16, 20, 28, 32     | In-phase (+) digital outputs first phase demultiplexer (channel Q) DOAI0 is the LSB. DOAQ7 is the MSB                                |
| DOAQ0N, DOAQ1N, DOAQ2N, DOAQ3N, DOAQ4N, DOAQ5N, DOAQ6N, DOAQ7N | 135, 139, 3, 7, 15, 19, 27, 31     | Inverted phase (–) digital outputs first phase demultiplexer (channel Q) DOAI0N is the LSB. DOAQ7N is the MSB                        |
| DOBQ0, DOBQ1, DOBQ2, DOBQ3, DOBQ4, DOBQ5, DOBQ6, DOBQ7         | 134, 138, 2, 6, 14, 18, 26, 30     | In-phase (+) digital outputs second phase demultiplexer (channel Q) DOBQ0 is the LSB. DOBQ7 is the MSB                               |
| DOBQ0N, DOBQ1N, DOBQ2N, DOBQ3N, DOBQ4N, DOBQ5N, DOBQ6N, DOBQ7N | 133, 137, 1, 5, 13, 17, 25, 29     | Inverted phase (–) digital outputs second phase demultiplexer (channel Q) DOBQ0N is the LSB. DOBQ7N is the MSB                       |
| DOIRI  | 75                                 | In-phase (+) out-of-range bit input (I phase) combined demultiplexer out-of-range is high on the leading edge of code 0 and code 256 |
| DOIRIN   | 76                                 | Inverted phase of output signal DOIRI  |
| DOIRQ  | 34                                 | In-phase (+) out-of-range bit input (Q phase) combined demultiplexer out-of-range is high on the leading edge of code 0 and code 256 |
| DOIRQN   | 33                                 | Inverted phase of output signal DOIRQ  |
| MODE   | 74                                 | Bit selection for 3-wire bus interface or nominal setting  |
| CLK  | 73                                 | Input clock for 3-wire bus interface   |
| DATA   | 72                                 | Input data for 3-wire bus  |
| LND  | 71                                 | Beginning and end of register line for 3-wire bus interface  |
| CLKOI  | 121                                | Output clock in-phase (+) channel I  |
| CLKOIN   | 122                                | Inverted phase (–) output clock channel I  |
| CLKOQ  | 132                                | Output clock in-phase (+) channel Q, 1/2 input clock frequency   |
| CLKOQN   | 131                                | Inverted phase (–) output clock channel Q  |
| VtestQ, VtestI   | 53, 52                             | Pins for internal test (to be left open)   |
| Cal  | 70                                 | Calibration output bit status  |
| Vdiode   | 35                                 | Positive node of diode used for die junction temperature measurements  |



### 9.1 Typical Full Power Input Bandwidth

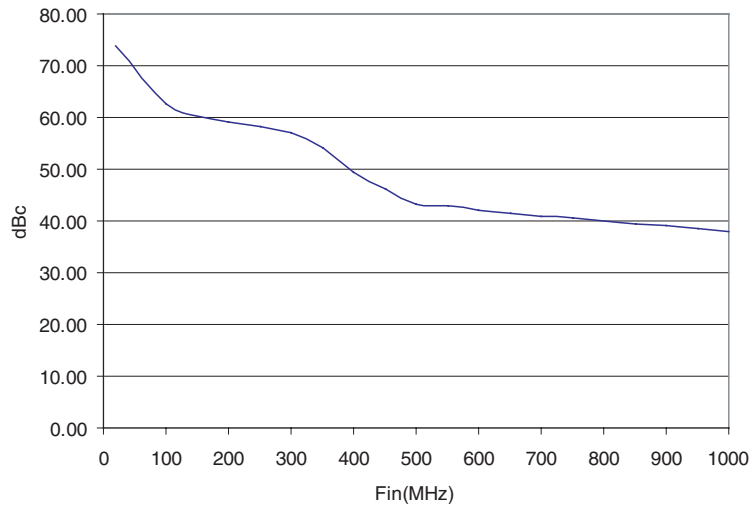
- $F_s = 500$  Msp/s
- $P_{clock} = 0$  dBm
- $P_{in} = -1$  dBFS
- Gain flatness ( $\pm 0.5$  dB) from DC to  $> 350$  MHz
- Full power input bandwidth at  $-3$  dB  $> 1$  GHz

Figure 9-1. Full Power Input Bandwidth



### 9.2 Typical Crosstalk

Figure 9-2. Crosstalk ( $F_s = 500$  Msp/s)

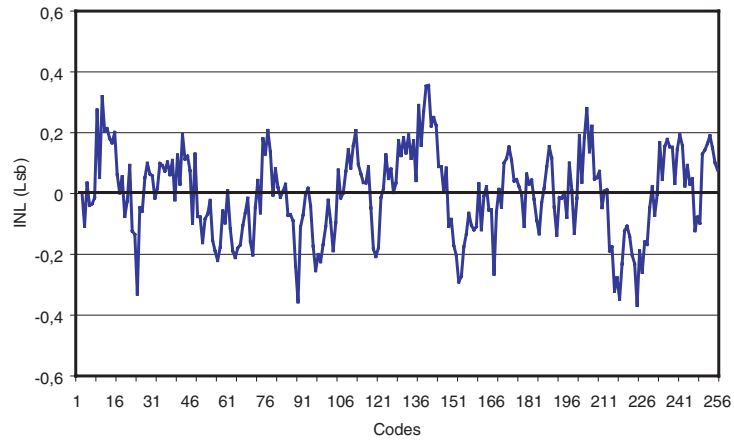


Note: Measured on the AT84AD004BTD-EB Evaluation Board.

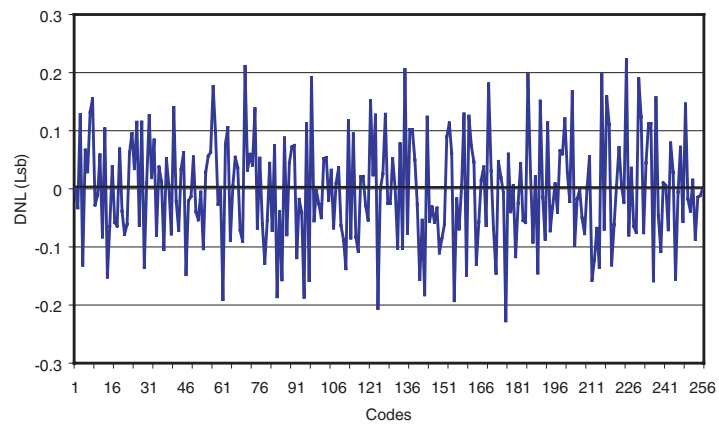
### 9.3 Typical DC, INL and DNL Patterns

1:2 DMUX mode,  $F_s/4$  DR type

**Figure 9-3.** Typical INL ( $F_s = 50$  Msps,  $F_{in} = 1$  MHz, Saturated Input)



**Figure 9-4.** Typical DNL (Fs = 50 Msps, Fin = 1 MHz, Saturated Input)





9.4 Typical Dynamic Performances Versus Sampling Frequency

Figure 9-5. ENOB Versus Sampling Frequency in Nyquist Conditions ( $F_{in} = F_s/2$ )

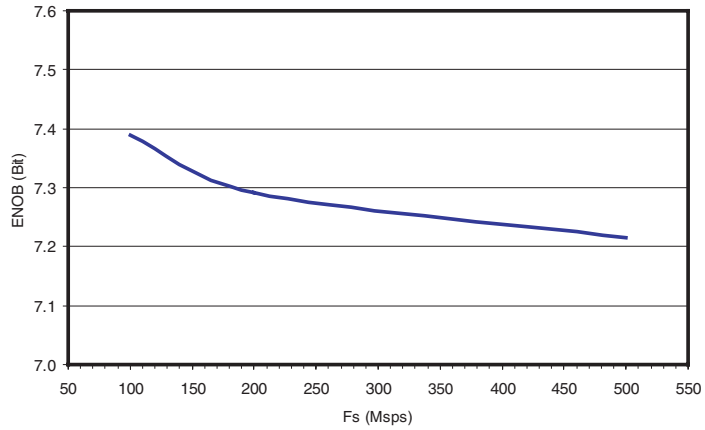


Figure 9-6. SFDR Versus Sampling Frequency in Nyquist Conditions ( $F_{in} = F_s/2$ )

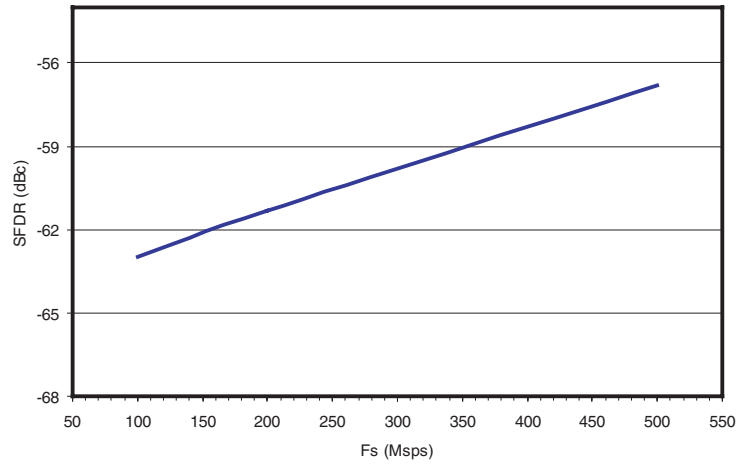
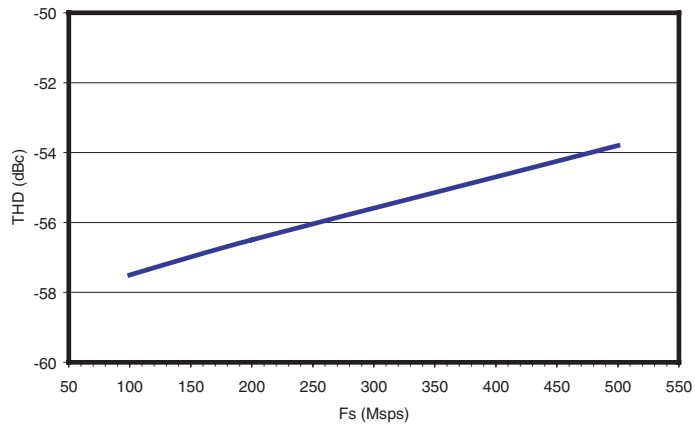
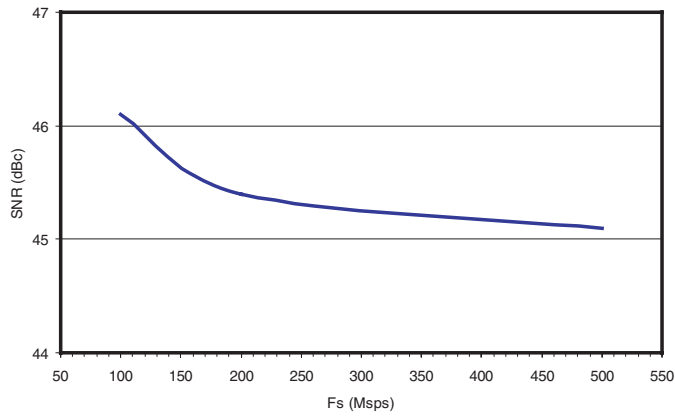


Figure 9-7. THD Versus Sampling Frequency in Nyquist Conditions ( $F_{in} = F_s/2$ )

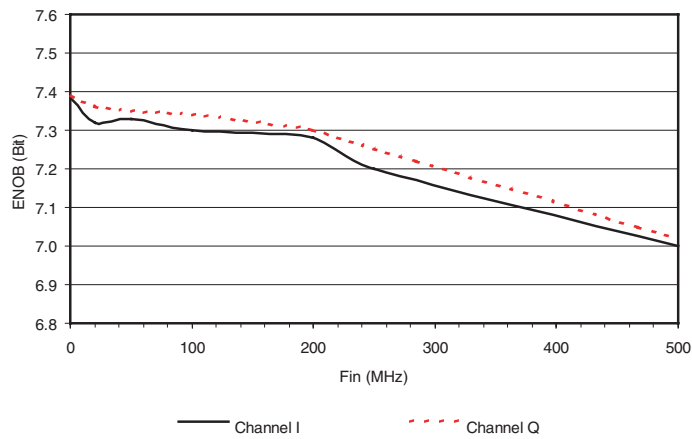


**Figure 9-8.** SNR Versus Sampling Frequency in Nyquist Conditions ( $F_{in} = F_s/2$ )



### 9.5 Typical Dynamic Performances Versus Input Frequency

**Figure 9-9.** ENOB Versus Input Frequency ( $F_s = 500$  MSPS)



**Figure 9-10.** SFDR Versus Input Frequency ( $F_s = 500$  MSPS)

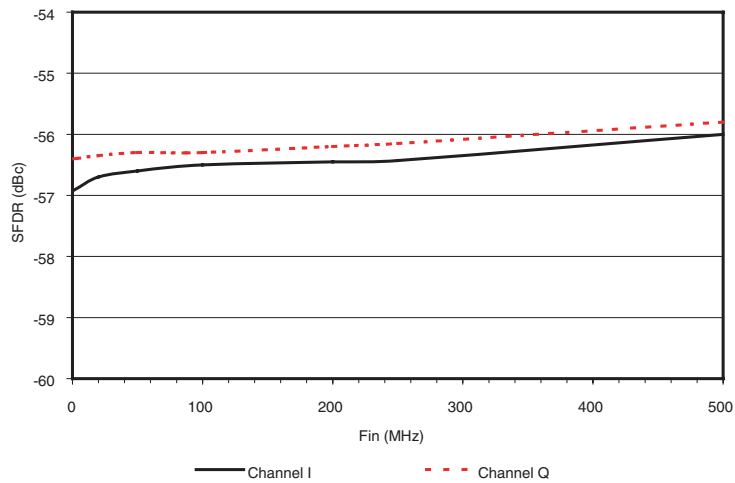


Figure 9-11. THD Versus Input Frequency (Fs = 500 Msps)

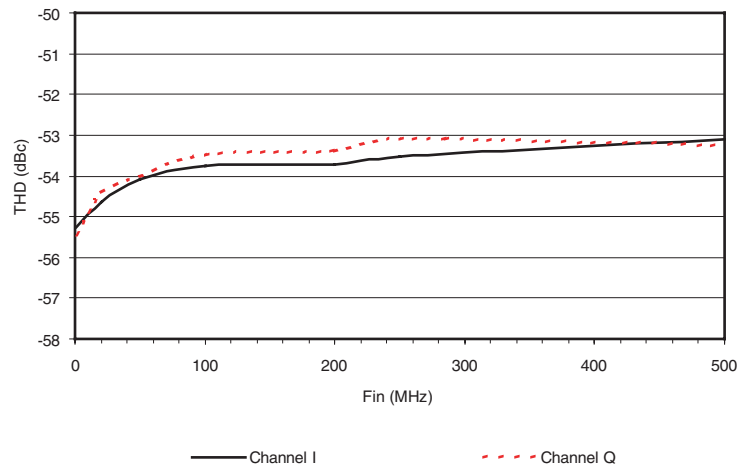
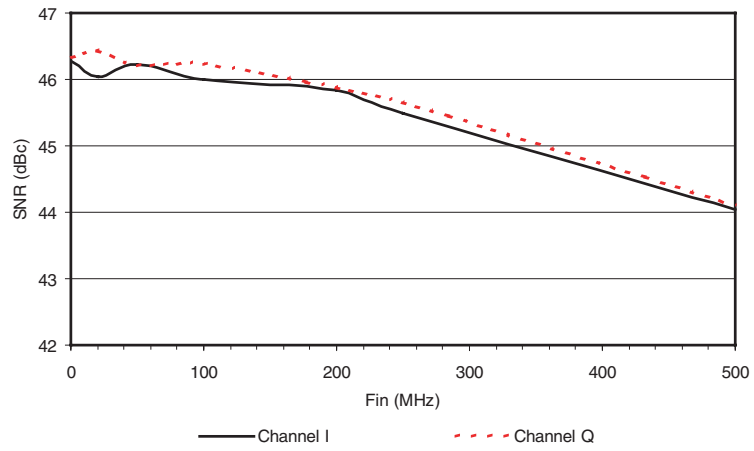
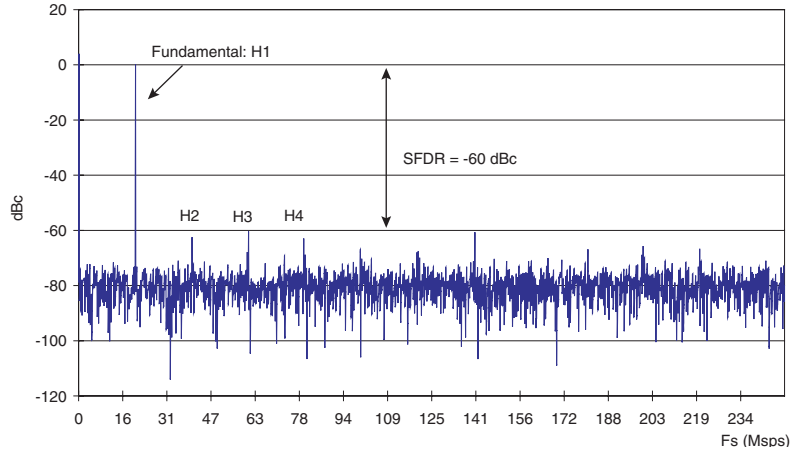


Figure 9-12. SNR Versus Input Frequency (Fs = 500 Msps)

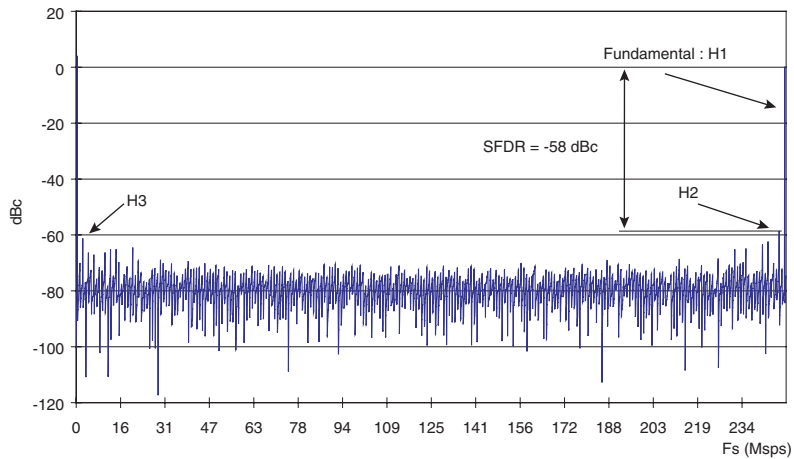


9.6 Typical Signal Spectrum

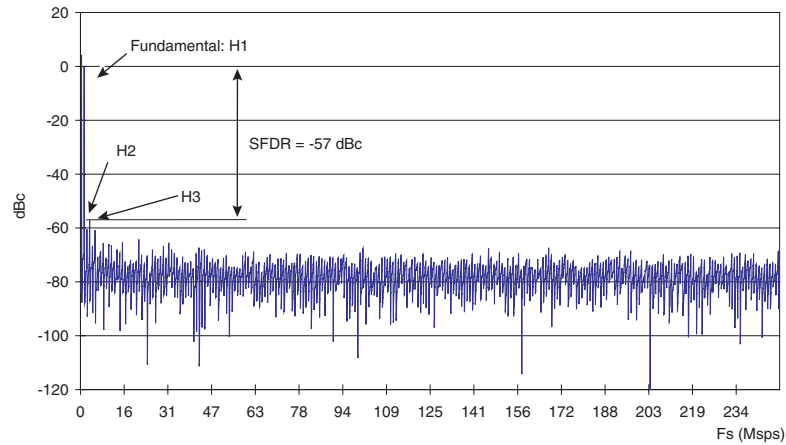
**Figure 9-13.**  $F_s = 500$  Mps and  $F_{in} = 20$  MHz (1:2 DMUX,  $F_s/4$  DR Type  
 $F_iSDA = -35$  ps,  $ISA = 0$  ps)



**Figure 9-14.**  $F_s = 500$  Mps and  $F_{in} = 250$  MHz (1:2 DMUX,  $F_s/4$  DR Type  
 $F_iSDA = -35$  ps,  $ISA = 0$  ps)

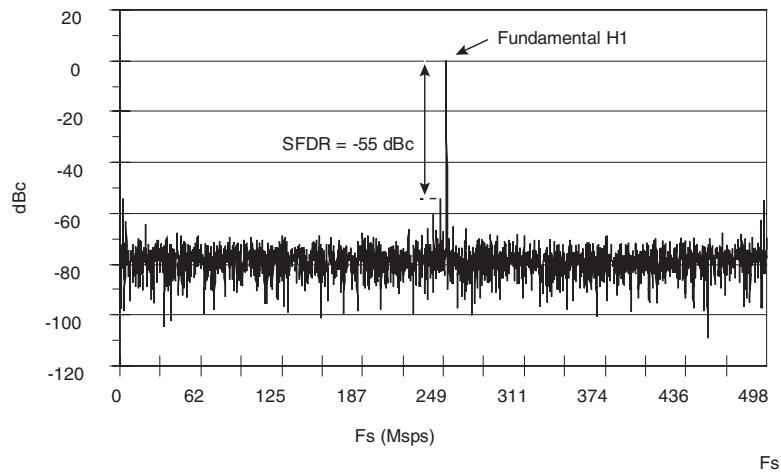


**Figure 9-15.**  $F_s = 500$  Msp/s and  $F_{in} = 500$  MHz (1:2 DMUX,  $F_s/4$  DR Type  
 $F_iSDA = -35$  ps,  $ISA = 0$  ps)



Note: The spectra are given with respect to the output clock frequency observed by the acquisition system (Figure 9-13 on page 28 to Figure 9-15).

**Figure 9-16.**  $F_s = 500$  Msp/s and  $F_{in} = 250$  MHz (Interleaving Mode  $F_{int} = 1$  Gsp/s  
 1:1 DMUX,  $F_iSDA = -35$  ps,  $ISA = 0$  ps)



9.7 Typical Performance Sensitivity Versus Power Supplies and Temperature

Figure 9-17. ENOB Versus  $V_{CCA}$  ( $F_s = 500$  Msps,  $F_{in} = 250$  MHz, 1:2 DMUX,  $F_s/4$  DR Type,  $ISA = 0$  ps)

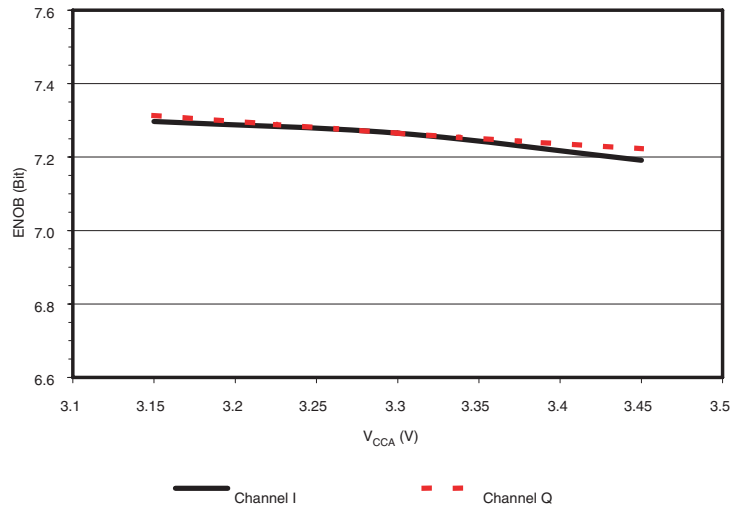
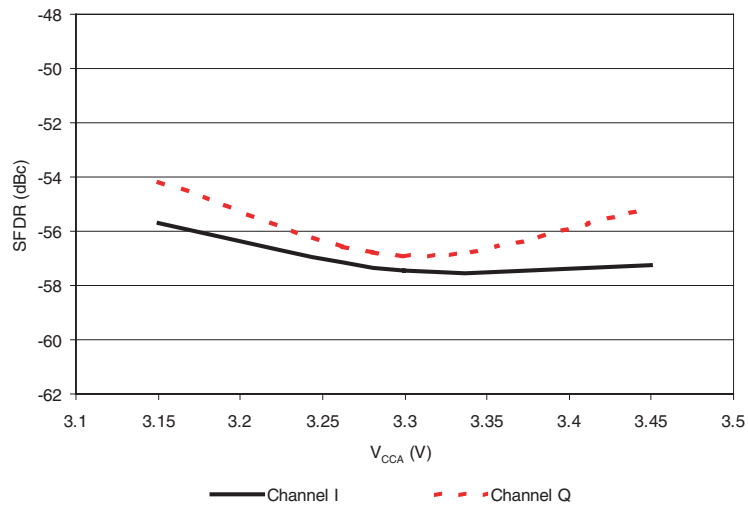
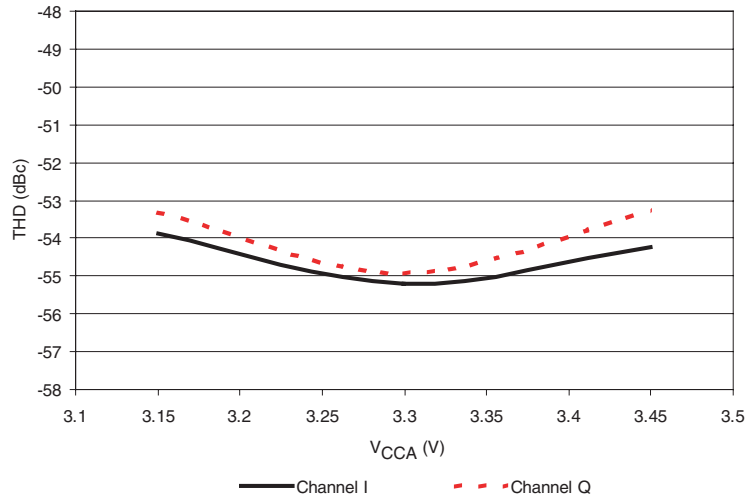


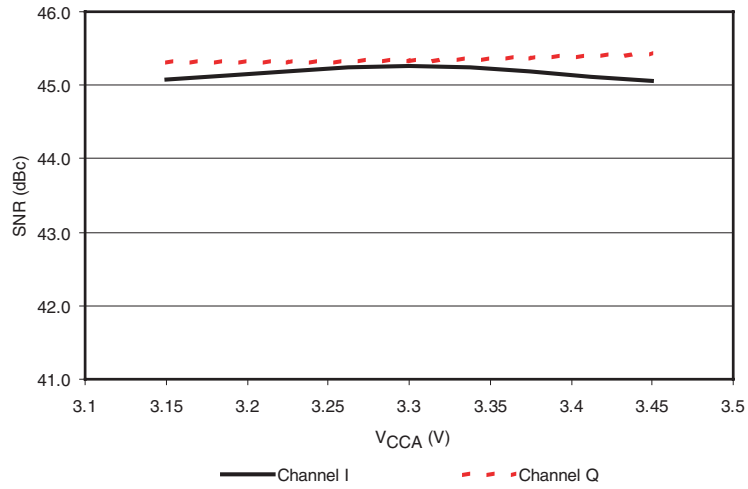
Figure 9-18. SFDR Versus  $V_{CCA}$  ( $F_s = 500$  Msps,  $F_{in} = 250$  MHz, 1:2 DMUX,  $F_s/4$  DR Type,  $ISA = 0$  ps)



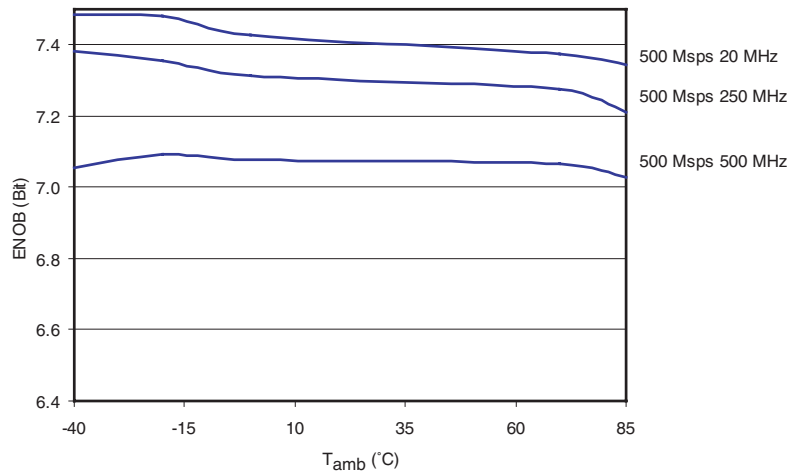
**Figure 9-19.** THD Versus  $V_{CCA}$  ( $F_s = 500$  Msp,  $F_{in} = 250$  MHz, 1:2 DMUX,  $F_s/4$  DR Type,  $ISA = 0$  ps)



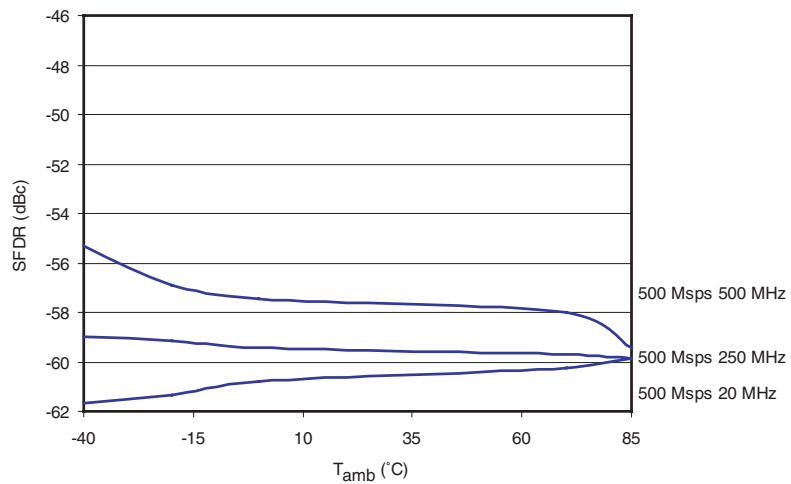
**Figure 9-20.** SNR Versus  $V_{CCA}$  ( $F_s = 500$  Msp,  $F_{in} = 250$  MHz, 1:2 DMUX,  $F_s/4$  DR Type,  $ISA = 0$  ps)



**Figure 9-21.** ENOB Versus Ambient Temperature ( $F_s = 500$  Msps,  $F_{in} = 250$  MHz, 1:2 DMUX,  $F_s/4$  DR Type)

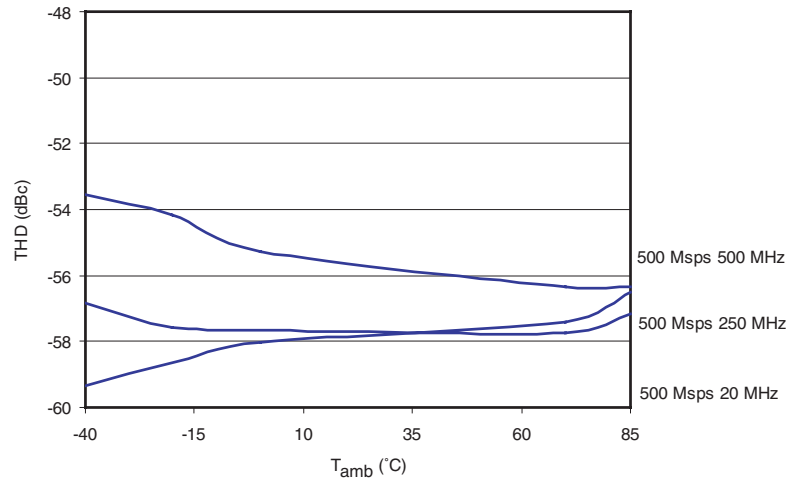


**Figure 9-22.** SFDR Versus Ambient Temperature ( $F_s = 500$  Msps,  $F_{in} = 250$  MHz, 1:2 DMUX,  $F_s/4$  DR Type)

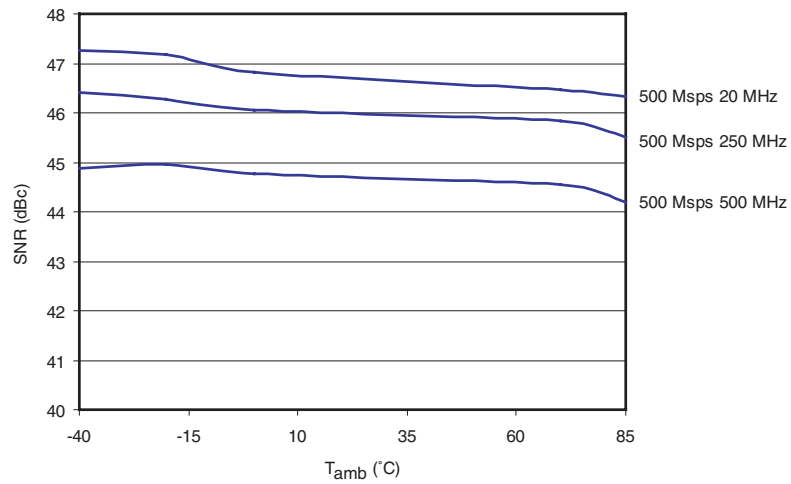




**Figure 9-23.** THD Versus Ambient Temperature (Fs = 500 Msps, Fin = 250 MHz, 1:2 DMUX, Fs/4 DR Type)



**Figure 9-24.** SNR Versus Ambient Temperature (Fs = 500 Msps, Fin = 250 MHz, 1:2 DMUX, Fs/4 DR Type)



## 10. Test and Control Features

### 10.1 3-wire Serial Interface Control Setting

**Table 10-1.** 3-wire Serial Interface Control Settings

| Mode             | Characteristics   |
|------------------|---|
| Mode = 1 (2.25V) | 3-wire serial bus interface activated   |
| Mode = 0 (0V)    | 3-wire serial bus interface deactivated<br>Nominal setting:<br>Dual channel I and Q activated<br>One clock I<br>0 dB gain<br>DMUX mode 1:1<br>DRDA I & Q = 0 ps<br>ISA I & Q = 0 ps<br>FiSDA Q = 0 ps<br>Binary output<br>Decimation test mode OFF<br>Calibration setting OFF<br>Data Ready = $F_s / 2$ |

10.1.1 3-wire Serial Interface and Data Description

The 3-wire bus is activated with the control bit mode set to 1. The length of the word is 19 bits: 16 for the data and 3 for the address. The maximum clock frequency is 50 MHz.

Table 10-2. 3-wire Serial Interface Address Setting Description

| Address | Setting  |
|---------|--|
| 000     | <b>Standby</b><br>Gray/binary mode<br>1:1 or 1:2 DMUX mode<br>Analog input MUX<br>Clock selection<br>Auto-calibration<br>Decimation test mode<br>Data Ready Delay Adjust   |
| 001     | <b>Analog gain adjustment</b><br>Data7 to Data0: gain channel I<br>Data15 to Data8: gain channel Q<br>Code 00000000: -1.5 dB<br>Code 10000000: 0 dB<br>Code 11111111: 1.5 dB<br>Steps: 0.011 dB  |
| 010     | <b>Offset compensation</b><br>Data7 to Data0: offset channel I<br>Data15 to Data8: offset channel Q<br>Data7 and Data15: sign bits<br>Code 11111111b: 31.75 LSB<br>Code 10000000b: 0 LSB<br>Code 00000000b: 0 LSB<br>Code 01111111b: -31.75 LSB<br>Steps: 0.25 LSB<br>Maximum correction: ±31.75 LSB |
| 011     | <b>Gain compensation</b><br>Data6 to Data0: channel I/Q (Q is matched to I)<br>Code 11111111b: -0.315 dB<br>Code 10000000b: 0 dB<br>Code 00000000b: 0 dB<br>Code 01111111b: 0.315 dB<br>Steps: 0.005 dB<br>Data6: sign bit   |
| 100     | <b>Internal Settling Adjustment (ISA)</b><br>Data2 to Data0: channel I<br>Data5 to Data3: channel Q<br>Data15 to Data6: 1000010000   |

Table 10-2. 3-wire Serial Interface Address Setting Description (Continued)

| Address | Setting  |
|---------|--|
| 101     | <b>Testability</b><br>Data3 to Data0 = 0000<br>Mode S/H transparent ..... OFF: Data4 = 0 ON: Data4 = 1<br>Data7 = 0<br>Data8 = 0   |
| 110     | <b>Built-In Test (BIT)</b><br>Data0 = 0 ..... BIT Inactive.. Data0 = 1 BIT Active<br>Data1 = 0 ..... Static BIT..... Data1 = 1 Dynamic BIT<br>If Data1 = 1, then Ports BI & BQ = Rising Ramp<br>..... Ports AI & AQ = Decreasing Ramp<br>If Data1 = 0, then Data2 to Data9 = Static Data for BIT<br>..... Ports BI & BQ = Data2 to Data9<br>..... Ports AI & AQ = NOT (Data2 to Data9) |
| 111     | <b>Data Ready Delay Adjust (DRDA)</b><br>Data2 to Data0: clock I<br>Data5 to Data3: clock Q<br>Steps: 140 ps<br>000: -560 ps<br>100: 0 ps<br>111: 420 ps<br><br><b>Fine Sampling Delay Adjustment (FiSDA) on channel Q</b><br>Data10 to Data6: channel Q<br>Steps: 8 ps<br>Data4: sign bit<br>Code 11000: -64 ps<br>Code 10000: 0 ps<br>Code 00000: 0 ps<br>Code 01111: 120 ps         |

- Notes:
- The Internal Settling Adjustment could change independently of the two analog sampling times (TA channels I and Q) of the sample/hold (with a fixed digital sampling time) with steps of  $\pm 50$  ps:  
 Nominal mode will be given by Data2...Data0 = 100 or Data5...Data3 = 100.  
 Data5...Data3 = 000 or Data2...Data0 = 000: sampling time is -200 ps compared to nominal.  
 Data2...Data0 = 111 or Data5...Data3 = 111: sampling time is 150 ps compared to nominal.  
 We recommend setting the ISA to 0 ps to optimize the ADC's dynamic performances.
  - The Fine Sampling Delay Adjustment enables you to change the sampling time (steps of  $\pm 5$  ps) on channel Q more precisely, particularly in the interleaved mode.
  - The "S/H transparent" mode (address 101, Data4) enables bypassing of the ADC's track/hold. This function optimizes the ADC's performances at very low input frequencies ( $F_{in} < 50$  MHz).
  - In the Gray mode, when the input signal is overflow (that is, the differential analog input is greater than 250 mV), the output data must be corrected using the output DOIR:  
 If DOIR = 1: Data7 unchanged  
 Data6 = 0, Data5 = 0, Data4 = 0, Data3 = 0, Data2 = 0, Data1 = 0, Data0 = 0.  
 In 1:2 DMUX mode, only one out-of-range bit is provided for both A and B ports.
  - With DRDA adjustment, you can shift the Output clock signal (shift the falling and rising edges) from -560 to +420 ps around its default value.

**Table 10-3.** 3-wire Serial Interface Data Setting Description

| Setting for Address: 000   | D15 | D14 | D13 | D12 | D11 | D10 | D9 <sup>(1)</sup> | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|--|-----|-----|-----|-----|-----|-----|-------------------|----|----|----|----|----|----|----|----|----|
| Full standby mode  | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | X  | 1  | 1  |
| Standby channel I <sup>(2)</sup>   | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | X  | 0  | 1  |
| Standby channel Q <sup>(3)</sup>   | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | X  | 1  | 0  |
| No standby mode  | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | X  | 0  | 0  |
| Binary output mode   | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | 1  | X  | X  |
| Gray output mode   | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | 0  | X  | X  |
| DMUX 1:2 mode  | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | 1  | X  | X  | X  |
| DMUX 1:1 mode  | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | 0  | X  | X  | X  |
| Analog selection mode<br>Input I → ADC I<br>Input Q → ADC Q                      | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | 1  | 1  | X  | X  | X  | X  |
| Analog selection mode<br>Input I → ADC I<br>Input I → ADC Q                      | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | 1  | 0  | X  | X  | X  | X  |
| Analog selection mode<br>Input Q → ADC I<br>Input Q → ADC Q                      | X   | X   | X   | X   | X   | X   | 0                 | X  | X  | X  | 0  | X  | X  | X  | X  | X  |
| Clock Selection mode<br>CLKI → ADC I<br>CLKQ → ADC Q                             | X   | X   | X   | X   | X   | X   | 0                 | X  | 1  | 1  | X  | X  | X  | X  | X  | X  |
| Clock selection mode<br>CLKI → ADC I<br>CLKI → ADC Q                             | X   | X   | X   | X   | X   | X   | 0                 | X  | 1  | 0  | X  | X  | X  | X  | X  | X  |
| Clock selection mode<br>CLKI → ADC I<br>CLKIN → ADC Q                            | X   | X   | X   | X   | X   | X   | 0                 | X  | 0  | X  | X  | X  | X  | X  | X  | X  |
| Decimation OFF mode  | X   | X   | X   | X   | X   | X   | 0                 | 0  | X  | X  | X  | X  | X  | X  | X  | X  |
| Decimation ON mode   | X   | X   | X   | X   | X   | X   | 0                 | 1  | X  | X  | X  | X  | X  | X  | X  | X  |
| Keep last calibration<br>calculated value <sup>(4)</sup><br>No calibration phase | X   | X   | X   | X   | 0   | 1   | 0                 | X  | X  | X  | X  | X  | X  | X  | X  | X  |
| No calibration phase <sup>(5)</sup><br>No calibration value                      | X   | X   | X   | X   | 0   | 0   | 0                 | X  | X  | X  | X  | X  | X  | X  | X  | X  |
| Start a new calibration phase  | X   | X   | X   | X   | 1   | 1   | 0                 | X  | X  | X  | X  | X  | X  | X  | X  | X  |
| Control wait bit calibration <sup>(6)</sup>                                      | X   | X   | a   | b   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | X  | X  | X  |
| In 1:2 DMUX<br>FDataReady<br>I & Q = Fs/2  | X   | 0   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | X  | X  | X  |
| In 1:2 DMUX<br>FDataReady<br>I & Q = Fs/4  | X   | 1   | X   | X   | X   | X   | 0                 | X  | X  | X  | X  | X  | X  | X  | X  | X  |

- Notes: 1. D9 must be set to "0"  
 2. Mode standby channel I: use analog input I Vini, Vinib and Clocki.

3. Mode standby channel Q: use analog input Q Vinq, Vinqb and Clockq.
4. Keep last calibration calculated value – no calibration phase: D11 = 0 and D10 = 1. No new calibration is required. The values taken into account for the gain and offset are either from the last calibration phase or are default values (reset values).
5. No calibration phase – no calibration value: D11 = 0 and D10 = 0. No new calibration phase is required. The gain and offset compensation functions can be accessed externally by writing in the registers at address 010 for the offset compensation and at address 011 for the gain compensation.
6. The control wait bit gives the possibility to change the internal setting for the auto-calibration phase:
  - For high clock rates (= 500 Msps) use a = b = 1.
  - For clock rates > 250 Msps and < 500 Msps use a = 1 and b = 0.
  - For clock rates > 125 Msps and < 250 Msps use a = 0 and b = 1.
  - For low clock rates < 125 Msps use a = 0 and b = 0.
7. When Channel I is in standby (D1 = 0, D0 = 1), the following modes are forbidden:
  - Clock I: I & Q (D7 = 1, D6 = 0)
  - Clock I: I & Clock IN: Q (D7 = 0, D6 = X)
8. If the partial standby mode is necessary in an application, we highly recommend to use the “Standby Q” function and apply the clock signal on channel I instead of using the “Standby I” function and using the clock Q signal;

### 10.1.2 3-wire Serial Interface Timing Description

The 3-wire serial interface is a synchronous write-only serial interface made of three wires:

- sclk: serial clock input
- sldn: serial load enable input
- sdata: serial data input

The 3-wire serial interface gives write-only access to as many as 8 different internal registers of up to 16 bits each. The input format is always fixed with 3 bits of register address followed by 16 bits of data. The data and address are entered with the Most Significant Bit (MSB) first.

The write procedure is fully synchronous with the rising clock edge of “sclk” and described in the write chronogram ([Figure 10-1 on page 39](#)).

- “sldn” and “sdata” are sampled on each rising clock edge of “sclk” (clock cycle).
- “sldn” must be set to 1 when no write procedure is performed.
- A minimum of one rising clock edge (clock cycle) with “sldn” at 1 is required for a correct start of the write procedure.
- A write starts on the first clock cycle with “sldn” at 0. “sldn” must stay at 0 during the complete write procedure.
- During the first 3 clock cycles with “sldn” at 0, 3 bits of the register address from MSB (a[2]) to LSB (a[0]) are entered.
- During the next 16 clock cycles with “sldn” at 0, 16 bits of data from MSB (d[15]) to LSB (d[0]) are entered.
- An additional clock cycle with “sldn” at 0 is required for parallel transfer of the serial data d[15:0] into the addressed register with address a[2:0]. This yields 20 clock cycles with “sldn” at 0 for a normal write procedure.
- A minimum of one clock cycle with “sldn” returned at 1 is requested to close the write procedure and make the interface ready for a new write procedure. Any clock cycle where “sldn” is at 1 *before* the write procedure is completed interrupts this procedure and no further data transfer to the internal registers is performed.
- Additional clock cycles with “sldn” at 0 *after* the parallel data transfer to the register (done at the 20th consecutive clock cycle with “sldn” at 0) do not affect the write procedure and are ignored.

It is possible to have only one clock cycle with “sldn” at 1 between two following write procedures.

- 16 bits of data must always be entered even if the internal addressed register has less than 16 bits. Unused bits (usually MSBs) are ignored. Bit signification and bit positions for the internal registers are detailed in [Table 10-2 on page 35](#).

To reset the registers, the Pin mode can be used as a reset pin for chip initialization, even when the 3-wire serial interface is used.

Figure 10-1. Write Chronogram

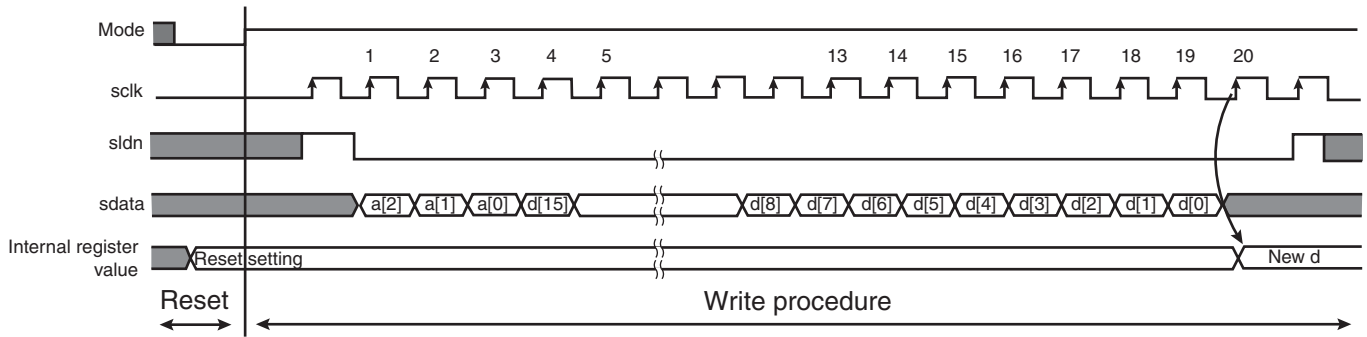


Figure 10-2. Timing Definition

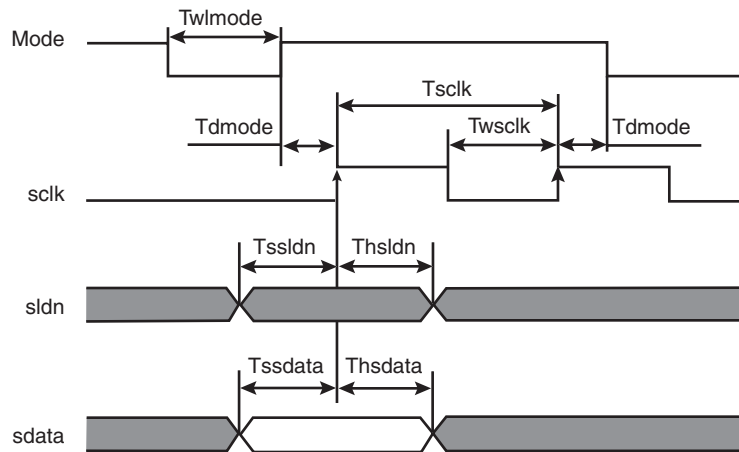


Table 10-4. Timing Description

| Name    | Parameter   | Value |     |     | Unit |
|---------|---|-------|-----|-----|------|
|         |   | Min   | Typ | Max |      |
| Tscclk  | Scclk period  | 20    |     |     | ns   |
| Twscclk | High or low time of sclk  | 5     |     |     | ns   |
| Tssldn  | Setup time of sldn before rising edge of sclk                     | 4     |     |     | ns   |
| Thsldn  | Hold time of sldn after rising edge of sclk                       | 2     |     |     | ns   |
| Tssdata | Setup time of sdata before rising edge of sclk                    | 4     |     |     | ns   |
| Thsdata | Hold time of sdata after rising edge of sclk                      | 2     |     |     | ns   |
| Twlmode | Minimum low pulse width of mode                                   | 5     |     |     | ns   |
| Tdmode  | Minimum delay between an edge of mode and the rising edge of sclk | 10    |     |     | ns   |

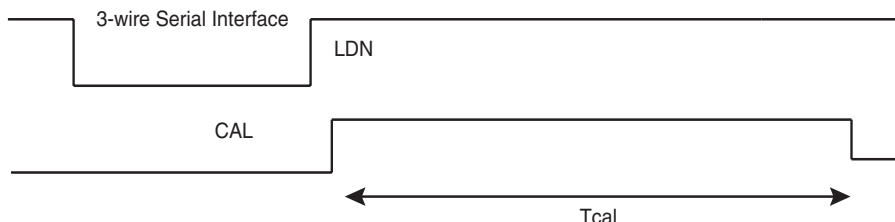
**10.1.3 Calibration Description**

The AT84AD004B offers the possibility of reducing offset and gain matching between the two ADC cores. An internal digital calibration may start right after the 3-wire serial interface has been loaded (using data D12 of the 3-wire serial interface with address 000).

The beginning of calibration disables the two ADCs and a standard data acquisition is performed. The output bit CAL goes to a high level during the entire calibration phase. When this bit returns to a low level, the two ADCs are calibrated with offset and gain and can be used again for a standard data acquisition.

If only one channel is selected (I or Q) the offset calibration duration is divided by two and no gain calibration between the two channels is necessary.

**Figure 10-3.** Internal Timing Calibration



The Tcal duration is a multiple of the clock frequency ClockI (master clock). Even if a dual clock scheme is used during calibration, ClockQ will not be used.

The control wait bits (D13 and D14) give the possibility of changing the calibration's setting depending on the clock's frequency:

- For high clock rates (= 500 Msps) use a = b = 1, Tcal = 10112 clock I periods.
- For clock rates > 250 Msps and < 500 Msps use a = 1, b = 0, Tcal = 6016 clock I periods.
- For clock rates > 125 Msps and < 250 Msps use a = 0, b = 1, Tcal = 3968 clock I periods.
- For low clock rates (< 125 Msps) use a = 0, b = 0, Tcal = 2944 clock I periods.

The calibration phase is necessary when using the AT84AD004B in interleaved mode, where one analog input is sampled at both ADC cores on the common input clock's rising and falling edges. This operation is equivalent to converting the analog signal at twice the clock frequency

**Table 10-5.** Matching Between Channels

| Parameter  | Value |       |     | Unit |
|--|-------|-------|-----|------|
|  | Min   | Typ   | Max |      |
| Gain error (single channel I or Q) without calibration       |       | 0     |     | %    |
| Gain error (single channel I or Q) with calibration          | -2    | 0     | 2   | %    |
| Offset error (single channel I or Q) without calibration     |       | 0     |     | LSB  |
| Offset error (single channel I or Q) with calibration        | -2    | 0     | 2   | LSB  |
| Mean offset code without calibration (single channel I or Q) |       | 127.5 |     |      |
| Mean offset code with calibration (single channel I or Q)    | 126   | 127.5 | 129 |      |



During the ADC’s auto-calibration phase, the dual ADC is set with the following:

- Decimation mode ON
- 1:1 DMUX mode
- Binary mode

Any external action applied to any signal of the ADC’s registers is inhibited during the calibration phase.

**10.1.4 Gain and Offset Compensation Functions**

It is also possible for the user to have external access to the ADC’s gain and offset compensation functions:

- Offset compensation between I and Q channels (at address 010)
- Gain compensation between I and Q channels (at address 011)

To obtain manual access to these two functions, which are used to set the offset to middle code 127.5 and to match the gain of channel Q with that of channel I (if only one channel is used, the gain compensation does not apply), it is necessary to set the ADC to “manual” mode by writing 0 at bits D11 and D10 of address 000.

**10.1.5 Built-in Test (BIT)**

A Built-in Test (BIT) function is available to allow rapid testing of the device’s I/O by either applying a defined static pattern to the ADC or by generating a dynamic ramp at the ADC’s output. This function is controlled via the 3-wire bus interface at address 101.

- The BIT is active when Data0 = 1 at address 110.
- The BIT is inactive when Data0 = 0 at address 110.
- The Data1 bit allows choosing between static mode (Data1 = 0) and dynamic mode (Data1 = 1).

When the static BIT is selected (Data1 = 0), it is possible to write any 8-bit pattern by defining the Data9 to Data2 bits. Port B then outputs an 8-bit pattern equal to *Data9 ... Data2*, and Port A outputs an 8-bit pattern equal to *NOT (Data9 ... Data2)*.

**Example:**

Address = 110

Data =

|     |     |     |     |     |     |    |    |    |    |    |    |    |    |    |    |
|-----|-----|-----|-----|-----|-----|----|----|----|----|----|----|----|----|----|----|
| D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| X   | X   | X   | X   | X   | X   | 0  | 1  | 0  | 1  | 0  | 1  | 0  | 1  | 0  | 1  |

One should then obtain 01010101 on Port B and 10101010 on Port A.

When the dynamic mode is chosen (Data1 = 1) port B outputs a rising ramp while Port A outputs a decreasing one.

Note: In dynamic mode, use the DRDA function to align the edges of CLKO with the middle of the data.

**10.1.6 Decimation Mode**

The decimation mode is provided to enable rapid testing of the ADC. In decimation mode, one data out of 16 is output, thus leading to a maximum output rate of 31.25 Msps.

Note: Frequency (CLKO) = frequency (Data) = Frequency (CLKI)/16.

## 10.2 Die Junction Temperature Monitoring Function

A die junction temperature measurement setting is included on the board for junction temperature monitoring.

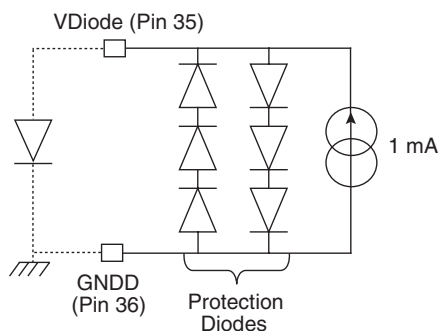
The measurement method forces a 1 mA current into a diode-mounted transistor.

Caution should be given to respecting the polarity of the current.

In any case, one should make sure the maximum voltage compliance of the current source is limited to a maximum of 1V or use a resistor serial-mounted with the current source to avoid damaging the transistor device (this may occur if the current source is reverse-connected).

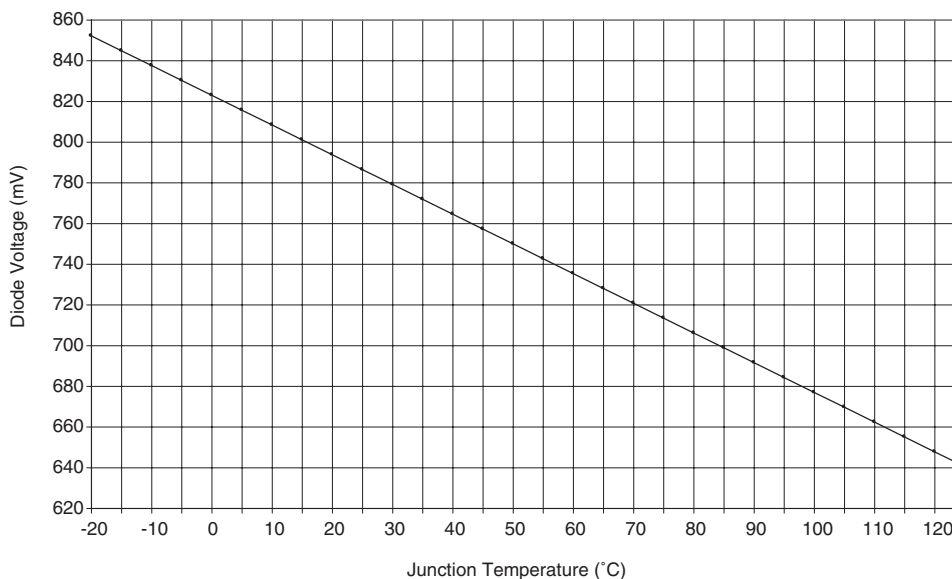
The measurement setup is illustrated in [Figure 10-4](#).

**Figure 10-4.** Die Junction Temperature Monitoring Setup



The VBE diode's forward voltage in relation to the junction temperature (in steady-state conditions) is shown in [Figure 10-5](#).

**Figure 10-5.** Diode Characteristics Versus  $T_J$



## 10.3 VtestI, VtestQ

VtestI and VtestQ pins are for internal test use only. These two signals must be left open.

## 11. Equivalent Input/Output Schematics

Figure 11-1. Simplified Input Clock Model

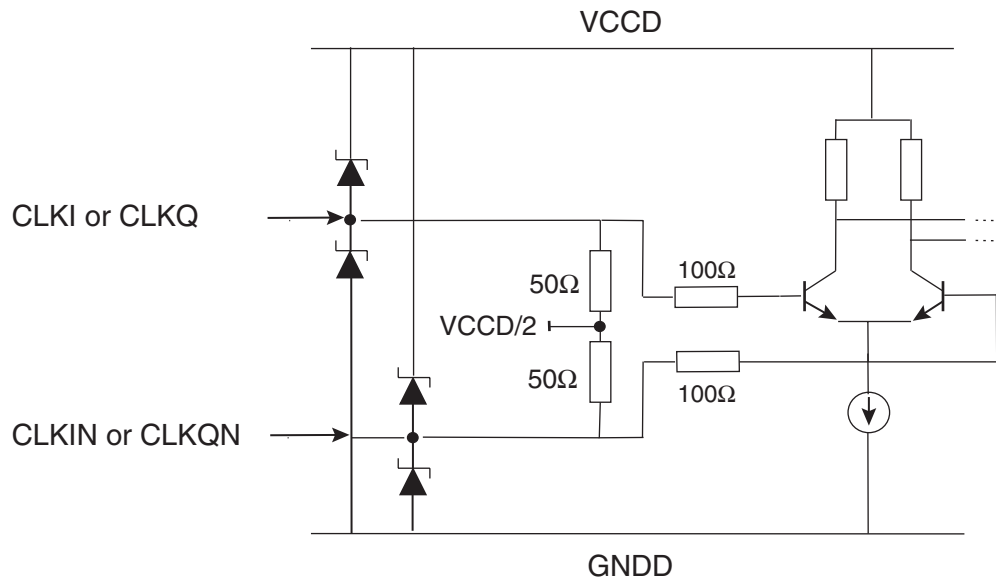
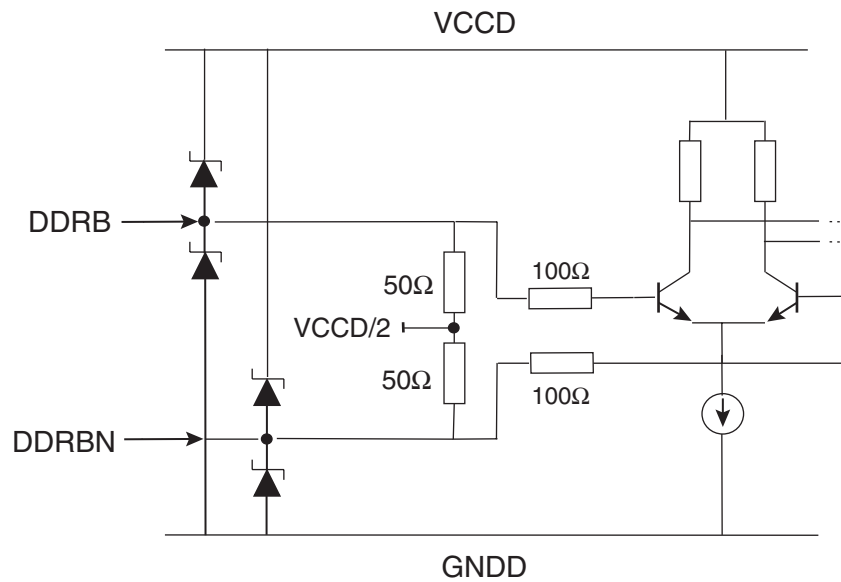


Figure 11-2. Simplified Data Ready Reset Buffer Model





## 12. Definitions of Terms

**Table 12-1.** Definitions of Terms

| Abbreviation | Definition                           | Description   |
|--------------|--------------------------------------|---|
| BER          | Bit Error Rate                       | The probability of an error occurring on the output at a maximum sampling rate.   |
| DNL          | Differential Non-Linearity           | The differential non-linearity for an output code <i>i</i> is the difference between the measured step size of code <i>i</i> and the ideal LSB step size. DNL ( <i>i</i> ) is expressed in LSBs. DNL is the maximum value of all DNL ( <i>i</i> ). A DNL error specification of less than 1 LSB guarantees that there are no missing output codes and that the transfer function is monotonic |
| ENOB         | Effective Number of Bits             | $ENOB = \frac{SINAD - 1.76 + 20 \log \left[ \frac{A}{F_s/2} \right]}{6.02}$ Where A is the actual input amplitude and <i>F<sub>s</sub></i> is the full scale range of the ADC under test  |
| FPBW         | Full Power Input Bandwidth           | The analog input frequency at which the fundamental component in the digitally reconstructed output waveform has fallen by 3 dB with respect to its low frequency value (determined by FFT analysis) for input at full-scale -1 dB (-1 dBFS)  |
| IMD          | Inter-Modulation Distortion          | The two tones intermodulation distortion (IMD) rejection is the ratio of either of the two input tones to the worst third order intermodulation products  |
| INL          | Integral Non-Linearity               | The integral non-linearity for an output code <i>i</i> is the difference between the measured input voltage at which the transition occurs and the ideal value of this transition. INL ( <i>i</i> ) is expressed in LSBs and is the maximum value of all IINL ( <i>i</i> )  |
| JITTER       | Aperture uncertainty                 | The sample-to-sample variation in aperture delay. The voltage error due to jitters depends on the slew rate of the signal at the sampling point   |
| NPR          | Noise Power Ratio                    | The NPR is measured to characterize the ADC's performance in response to broad bandwidth signals. When applying a notch-filtered broadband white noise signal as the input to the ADC under test, the Noise Power Ratio is defined as the ratio of the average out-of-notch to the average in-notch power spectral density magnitudes for the FFT spectrum of the ADC output sample test      |
| ORT          | Overvoltage Recovery Time            | The time to recover a 0.2% accuracy at the output, after a 150% full-scale step applied on the input is reduced to midscale   |
| PSRR         | Power Supply Rejection Ratio         | The ratio of input offset variation to a change in power supply voltage   |
| SFDR         | Spurious Free Dynamic Range          | The ratio expressed in dB of the RMS signal amplitude, set at 1 dB below full-scale, to the RMS value of the highest spectral component (peak spurious spectral component). The peak spurious component may or may not be a harmonic. It may be reported in dB (related to the converter -1 dB full-scale) or in dBc (related to the input signal level)                                      |
| SINAD        | Signal to Noise and Distortion Ratio | The ratio expressed in dB of the RMS signal amplitude, set to 1 dB below full-scale (-1 dBFS) to the RMS sum of all other spectral components including the harmonics, except DC  |
| SNR          | Signal to Noise Ratio                | The ratio expressed in dB of the RMS signal amplitude, set to 1 dB below full-scale, to the RMS sum of all other spectral components excluding the first 9 harmonics  |
| SSBW         | Small Signal Input Bandwidth         | The analog input frequency at which the fundamental component in the digitally reconstructed output waveform has fallen by 3 dB with respect to its low frequency value (determined by FFT analysis) for input at full-scale -10 dB (-10 dBFS)  |
| TA           | Aperture delay                       | The delay between the rising edge of the differential clock inputs (CLKI, CLKIN) [zero crossing point] and the time at which VIN and VINB are sampled   |
| TC           | Encoding Clock period                | TC1 = minimum clock pulse width (high)<br>TC = TC1 + TC2<br>TC2 = minimum clock pulse width (low)   |
| TD1          | Time delay data to clock             | Time delay between Data transition (Port A or B) channel I or Q to Output Clock CLKXO (channel I or Q)<br>If Output Clock CLKXO is in the middle to data TD1 = Tdata/2  |
| TD2          | Time delay clock to data             | Time delay between Output Clock CLKXO (channel I or Q) to Data transition (Port A or B) channel I or Q<br>If Output Clock CLKXO is in the middle to data TD2 = Tdata/2  |

Table 12-1. Definitions of Terms (Continued)

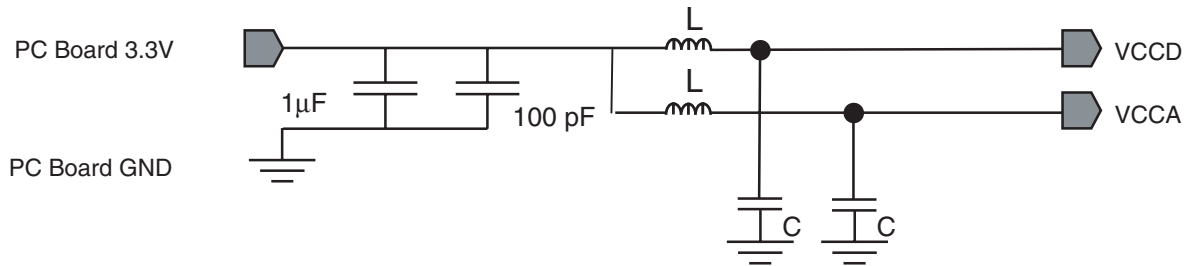
| Abbreviation | Definition                  | Description  |
|--------------|-----------------------------|--|
| TD1-TD2      |                             | This difference TD1-TD2 gives an information if Output Clock CLKXO (channel I or Q) is centered on the output data<br>If Output Clock CLKXO is in the middle to data $TD2=TD1=Tdata/2$   |
| TDO          | Digital Data Output Delay   | The delay from the rising edge of the differential clock inputs (CLKI, CLKIN) [zero crossing point] to the next point of change in the differential output data (zero crossing) with a specified load  |
| TDR          | Data Ready Output Delay     | The delay from the falling edge of the differential clock inputs (CLKI, CLKIN) [zero crossing point] to the next point of change in the differential output data (zero crossing) with a specified load   |
| TF           | Fall Time                   | The time delay for the output data signals to fall from 20% to 80% of delta between the low and high levels  |
| THD          | Total Harmonic Distortion   | The ratio expressed in dB of the RMS sum of the first 9 harmonic components to the RMS input signal amplitude, set at 1 dB below full-scale. It may be reported in dB (related to the converter -1 dB full-scale) or in dBc (related to the input signal level ) |
| TPD          | Pipeline Delay              | The number of clock cycles between the sampling edge of an input data and the associated output data made available (not taking into account the TDO)  |
| TR           | Rise Time                   | The time delay for the output data signals to rise from 20% to 80% of delta between the low and high levels  |
| TRDR         | Data Ready Reset Delay      | The delay between the falling edge of the Data Ready output asynchronous reset signal (DDRB) and the reset to digital zero transition of the Data Ready output signal (DR)   |
| TS           | Settling Time               | The time delay to rise from 10% to 90% of the converter output when a full-scale step function is applied to the differential analog input   |
| VSWR         | Voltage Standing Wave Ratio | The VSWR corresponds to the ADC input insertion loss due to input power reflection. For example, a VSWR of 1.2 corresponds to a 20 dB return loss (99% power transmitted and 1% reflected)   |

## 13. Using the AT84AD004B Dual 8-bit 500 Msp/s ADC

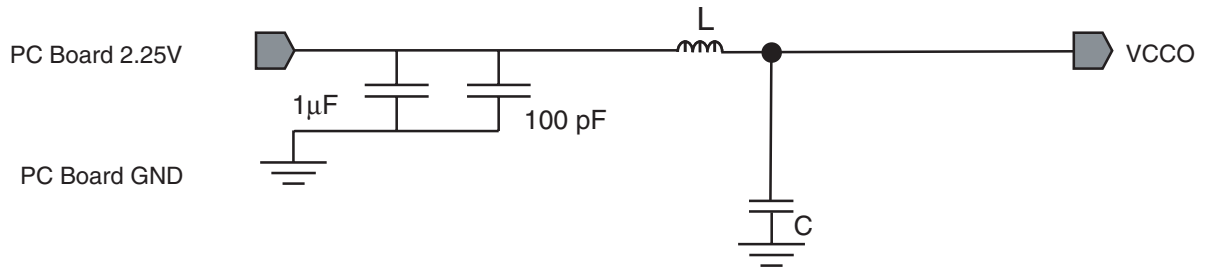
### 13.1 Decoupling, Bypassing and Grounding of Power Supplies

The following figures show the recommended bypassing, decoupling and grounding schemes for the dual 8-bit 500 Msp/s ADC power supplies.

**Figure 13-1.**  $V_{CCD}$  and  $V_{CCA}$  Bypassing and Grounding Scheme

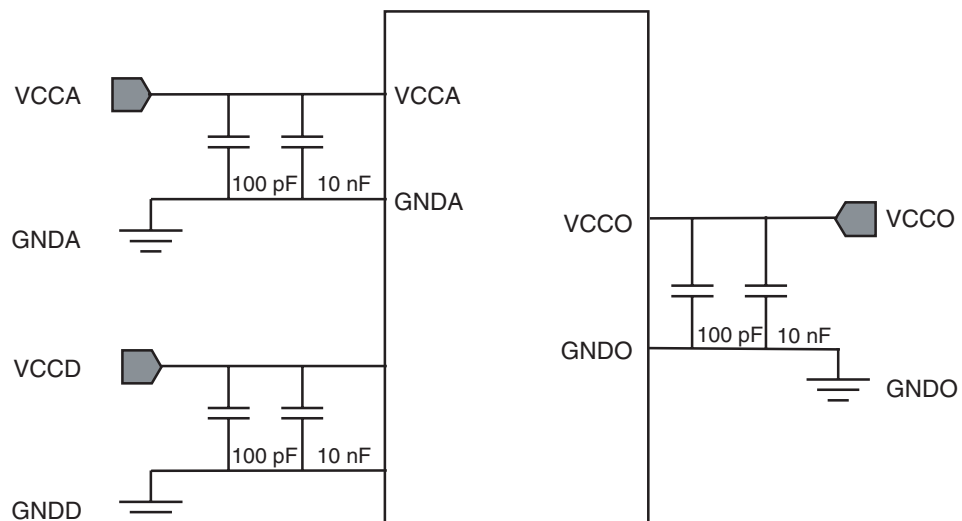


**Figure 13-2.**  $V_{CCO}$  Bypassing and Grounding Scheme



Note: L and C values must be chosen in accordance with the operating frequency of the application.

**Figure 13-3.** Power Supplies Decoupling Scheme



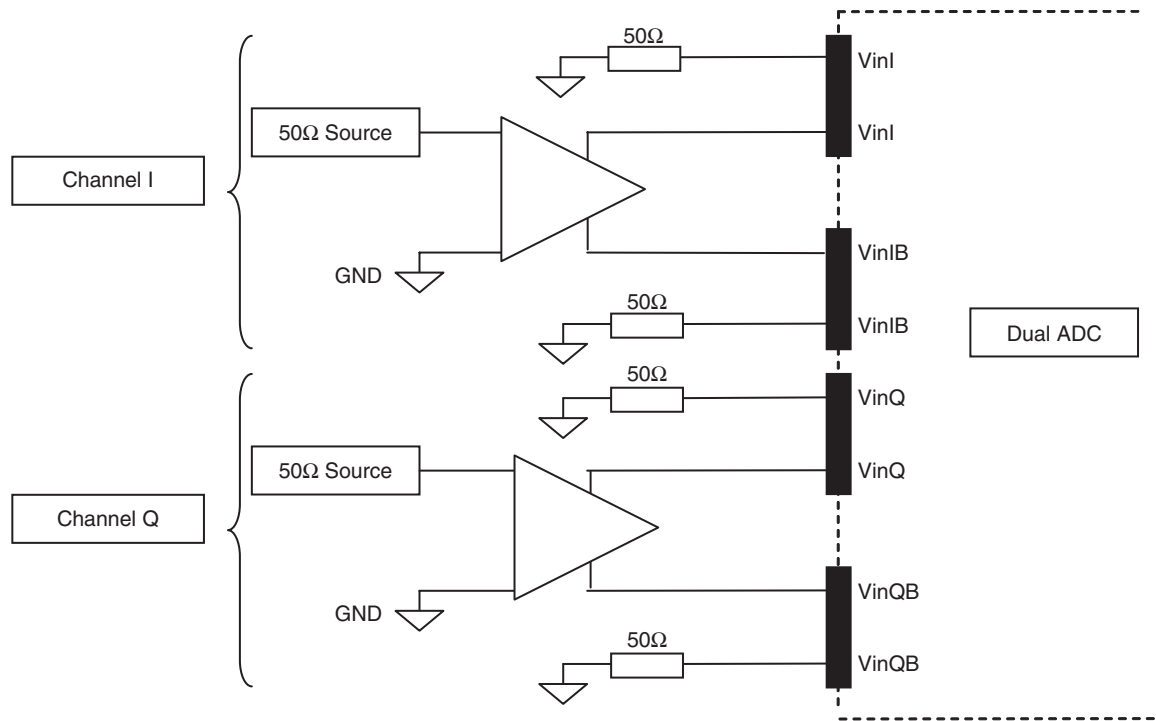
Note: The bypassing capacitors (1  $\mu$ F and 100 pF) should be placed as close as possible to the board connectors, whereas the decoupling capacitors (100 pF and 10 nF) should be placed as close as possible to the device.

## 13.2 Analog Input Implementation

The analog inputs of the dual ADC have been designed with a double pad implementation as illustrated in [Figure 13-4](#). The reverse pad for each input should be tied to ground via a  $50\Omega$  resistor.

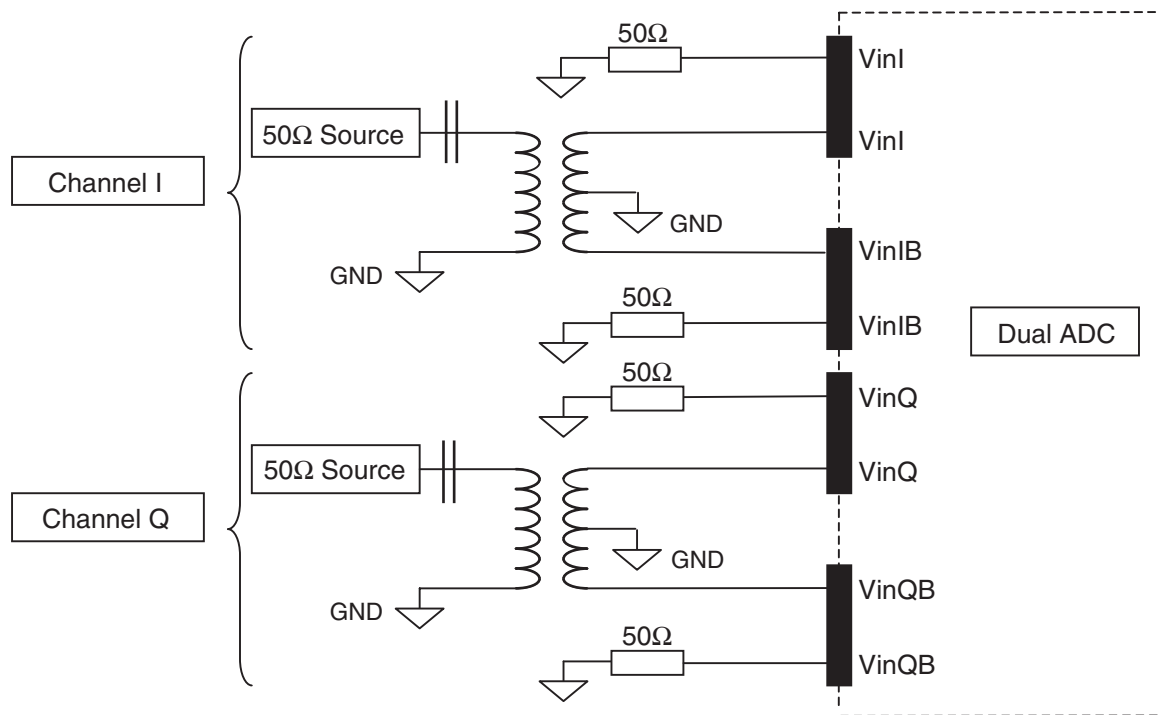
The analog inputs must be used in differential mode only.

**Figure 13-4.** Termination Method for the ADC Analog Inputs in DC Coupling Mode





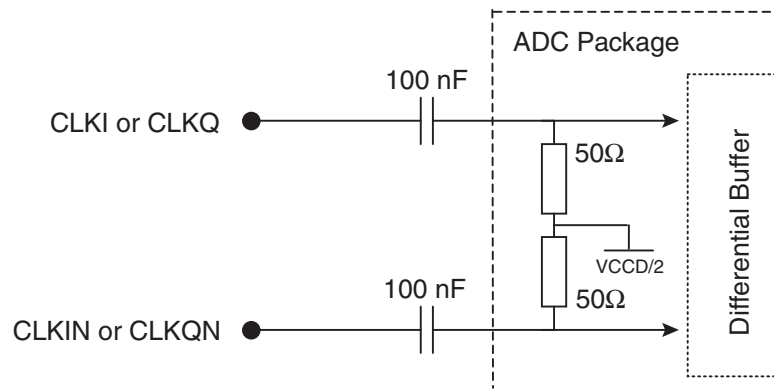
**Figure 13-5.** Termination Method for the ADC Analog Inputs in AC Coupling Mode



### 13.3 Clock Implementation

The ADC features two different clocks (I or Q) that must be implemented as shown in [Figure 13-6](#). Each path must be AC coupled with a 100 nF capacitor.

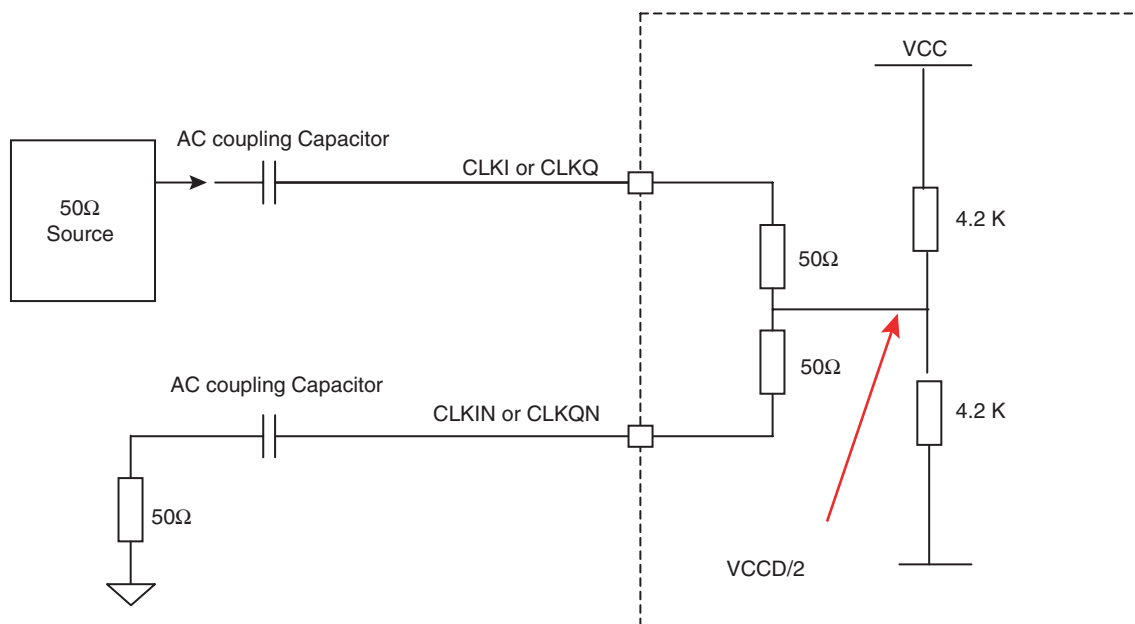
**Figure 13-6.** Differential Termination Method for Clock I or Clock Q



Note: When only clock I is used, it is not necessary to add the capacitors on the CLKQ and CLKQN signal paths; they may be left floating.

DDRB may be implemented as described in the following figure. A pull-up resistor is implemented to maintain the DDRB signal inactive in normal mode. The Data Ready Reset command (it may be a pulse) is active on the high level.

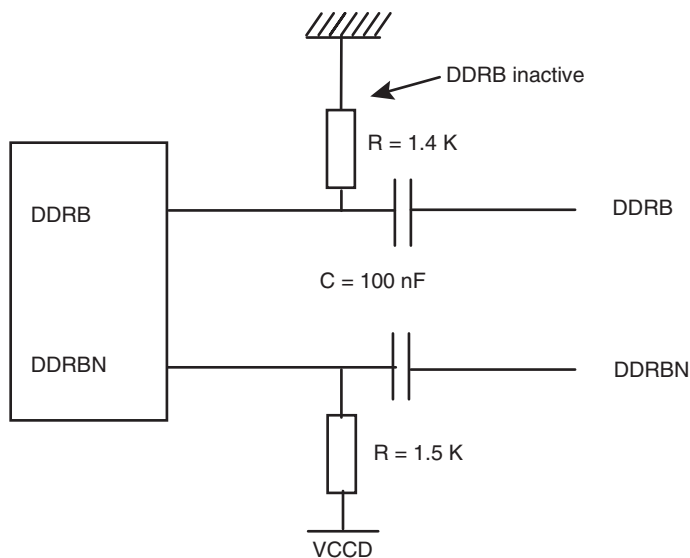
Figure 13-7. Single-ended Termination Method for Clock I or Clock Q



### 13.4 Reset Implementation

DDR<sub>B</sub> may be implemented as described in the following figure. A pull-up resistor is implemented to maintain the DDR<sub>B</sub> signal inactive in normal mode. The Data Ready Reset command (it might be a pulse) is active on the high level.

Figure 13-8. Reset Implementation



Note: The external pull up and pull down resistors are needed to bias the differential pair in AC coupling. They are of no use in DC coupling (when used with an LVDS driver).

### 13.5 Output Termination in 1:1 Ratio

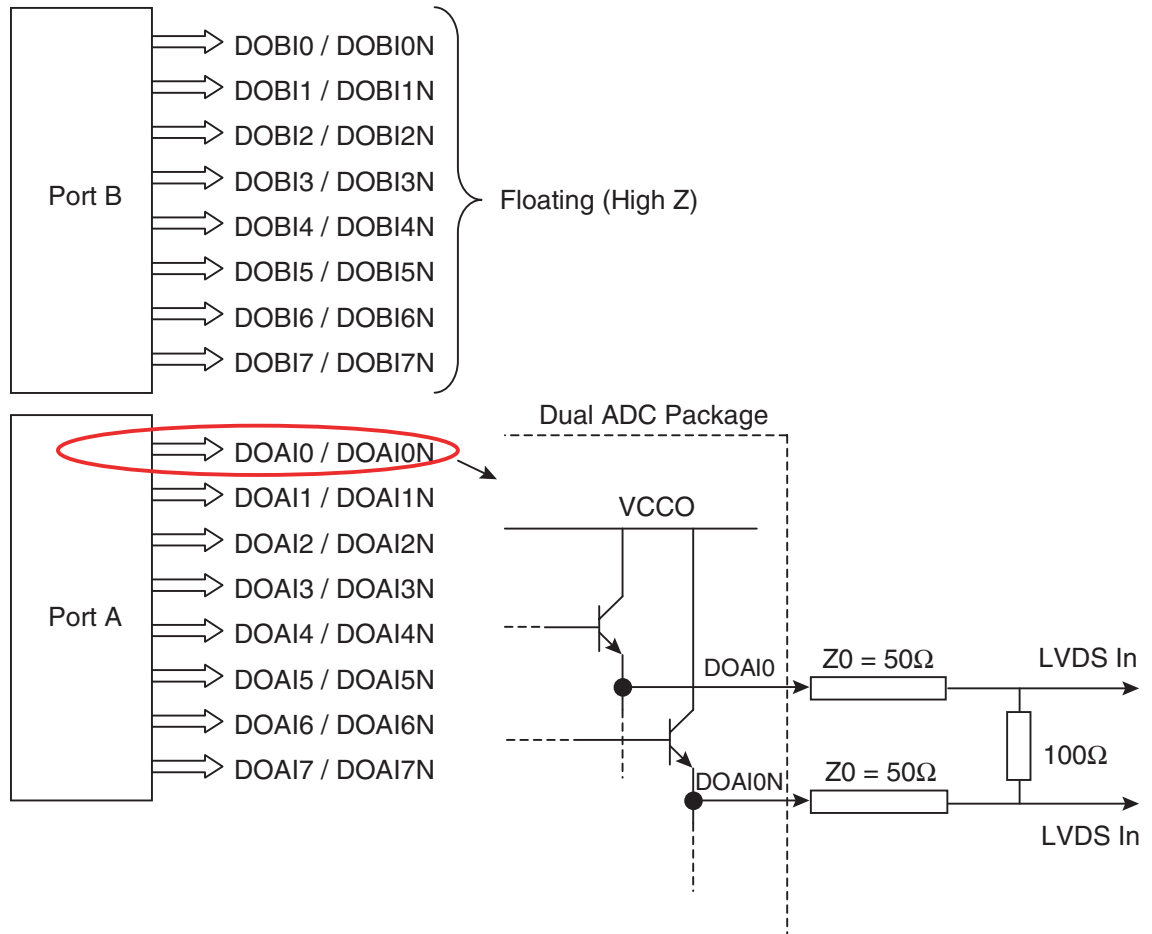
When using the integrated DMUX in 1:1 ratio, the valid port is port A. Port B remains unused.

Port A functions in LVDS mode and the corresponding outputs (DOAI or DOAQ) have to be 100Ω differentially terminated as shown in [Figure 13-9 on page 51](#).

The pins corresponding to Port B (DOBI or DOBQ pins) must be left floating (in high impedance state).

[Figure 13-9](#) is an example of a 1:1 ratio of the integrated DMUX for channel I (the same applies to channel Q).

**Figure 13-9.** Example of Termination for Channel I Used in DMUX 1:1 Ratio (Port B Unused)

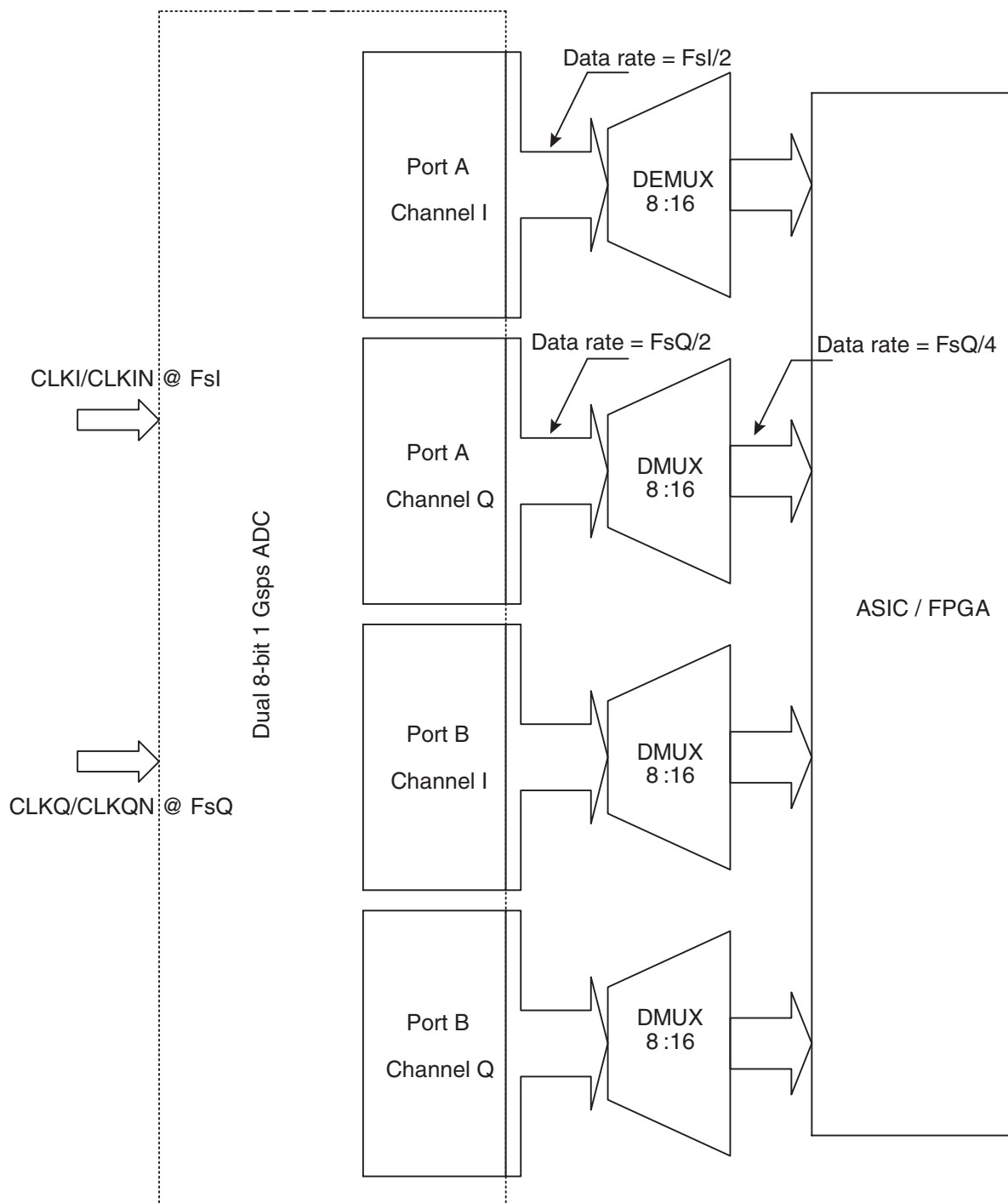


Note: If the outputs are to be used in single-ended mode, it is recommended that the true and false signals be terminated with a 50Ω resistor.

### 13.6 Using the Dual ADC With and ASIC/FPGA Load

Figure 13-10 on page 52 illustrates the configuration of the dual ADC (1:2 DMUX mode, independent I and Q clocks) driving an LVDS system (ASIC/FPGA) with potential additional DMUXes used to halve the speed of the dual ADC outputs.

Figure 13-10. Dual ADC and ASIC/FPGA Load Block Diagram



Note: The demultiplexers may be internal to the ASIC/FPGA system.

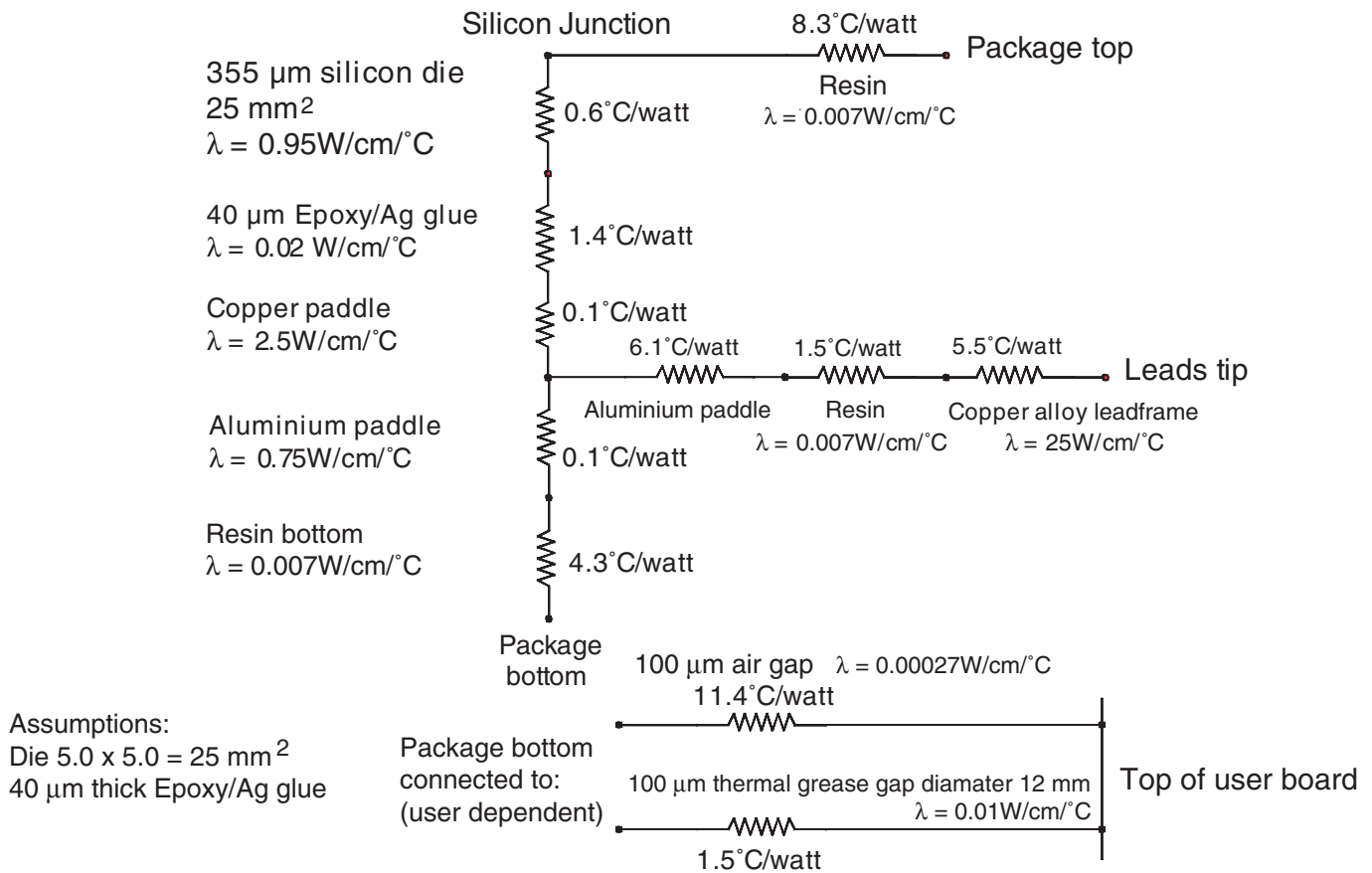
## 14. Thermal Characteristics

### 14.1 Simplified Thermal Model for LQFP 144 (20 × 20 × 1.4 mm)

The following model has been extracted from the ANSYS FEM simulations.

Assumptions: no air, no convection and no board.

Figure 14-1. Simplified Thermal Model for LQFP Package



Note: The above are typical values with an assumption of uniform power dissipation over 2.5 × 2.5 mm<sup>2</sup> of the top surface of the die.

#### 14.1.0.1 Thermal Resistance from Junction to Bottom of Leads

Assumptions: no air, no convection and no board.

The thermal resistance from the junction to the bottom of the leads is 15.2°C/W typical.

#### 14.1.0.2 Thermal Resistance from Junction to Top of Case

Assumptions: no air, no convection and no board.

The thermal resistance from the junction to the top of the case is 8.3°C/W typical.

#### 14.1.0.3 Thermal Resistance from Junction to Bottom of Case

Assumptions: no air, no convection and no board.

The thermal resistance from the junction to the bottom of the case is 6.4°C/W typical.

#### 14.1.0.4 Thermal Resistance from Junction to Bottom of Air Gap

The thermal resistance from the junction to the bottom of the air gap (bottom of package) is 17.9°C/W typical.

#### 14.1.0.5 Thermal Resistance from Junction to Ambient

The thermal resistance from the junction to ambient is 25.2°C/W typical.

Note: In order to keep the ambient temperature of the die within the specified limits of the device grade (that is  $T_{amb\ max} = 70^{\circ}\text{C}$  in commercial grade and  $85^{\circ}\text{C}$  in industrial grade) and the die junction temperature below the maximum allowed junction temperature of  $105^{\circ}\text{C}$ , it is necessary to operate the dual ADC in air flow conditions (1m/s recommended).

In still air conditions, the junction temperature is indeed greater than the maximum allowed  $T_J$ .

-  $T_J = 25.2^{\circ}\text{C/W} \times 1.4\text{W} + T_{amb} = 35.28 + 70 = 105.28^{\circ}\text{C}$  for commercial grade devices

-  $T_J = 25.2^{\circ}\text{C/W} \times 1.4\text{W} + T_{amb} = 35.28 + 85 = 125.28^{\circ}\text{C}$  for industrial grade devices

#### 14.1.0.6 Thermal Resistance from Junction to Board

The thermal resistance from the junction to the board is 13°C/W typical.

## 14.2 LQFP-ep 144L Green Package Thermal Characteristics

### 14.2.1 Thermal Resistance from Junction to Ambient

Simulations (JEDEC JESD51 standard) were held with the following assumptions:

- Board with 76.2 mm × 114.3 mm dimensions
- Still air
- Exposed pad (5.8 × 5.8 mm) soldered to the board

The thermal resistance from the junction to ambient is 25.0 °C/W.

Note: When the exposed pad is not soldered to the board, the  $R_{thj-a}$  becomes 58.8°C/W.

### 14.2.2 Exposed Pad Board layout Recommendation

This recommendation is done for the AT84AD004BXEPW (LQFP-ep 144L green package).

Electrical contact of the part to the Printed Circuit Board (PCB) is made by soldering the leads on the bottom surface of the package to the PCB. Hence; special attention is require to the heat transfer below the package to provide a good thermal bond to the PCB.

A Copper (Cu) fill is to be designed into PCB as a thermal pad under the package. Heat from devices, is conducted to the PCB at the thermal pad. It is then conducted from the thermal pad to the PCB inner ground plane by a 6.5 array of via. The LQFP metal died paddle must be soldered to the PCB's thermal pad.

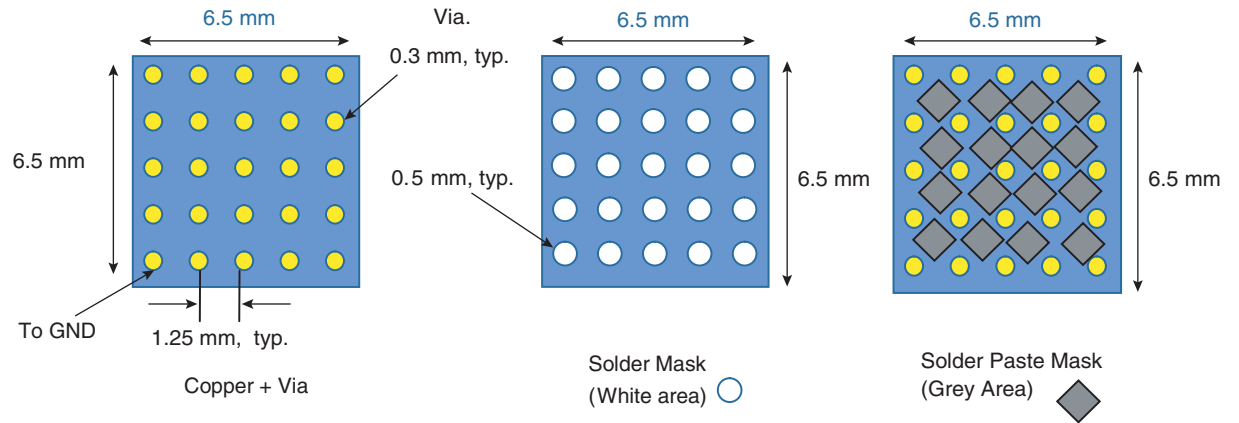
Solder mask is placed on the board top side over each via to resist solder flow into the via.

The diameter of solder Mask needs to be higher than diameter of via (diameter of via+ 0.2 mm)

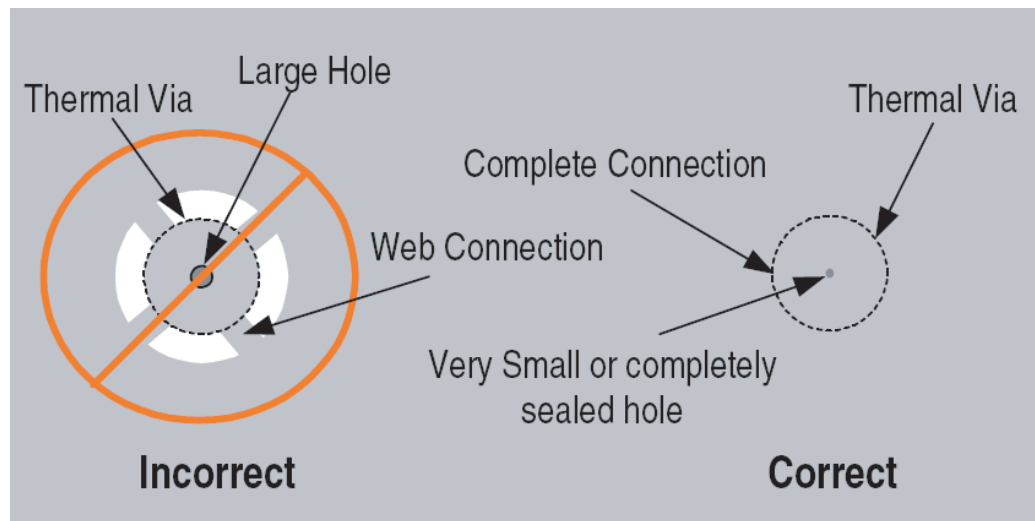
The diameter of solder Mask is 0.3 mm + 0.1 mm + 0.1 mm = 0.5 mm)

The Solder Paste template needs to de designed to allow at least 50% solder coverage.

The Solder Paste is place between the balls (diamond area) and not covers all the copper.



The thermal via is connect to inner layer (GND layer) with **complete connection**.



## 15. Ordering Information

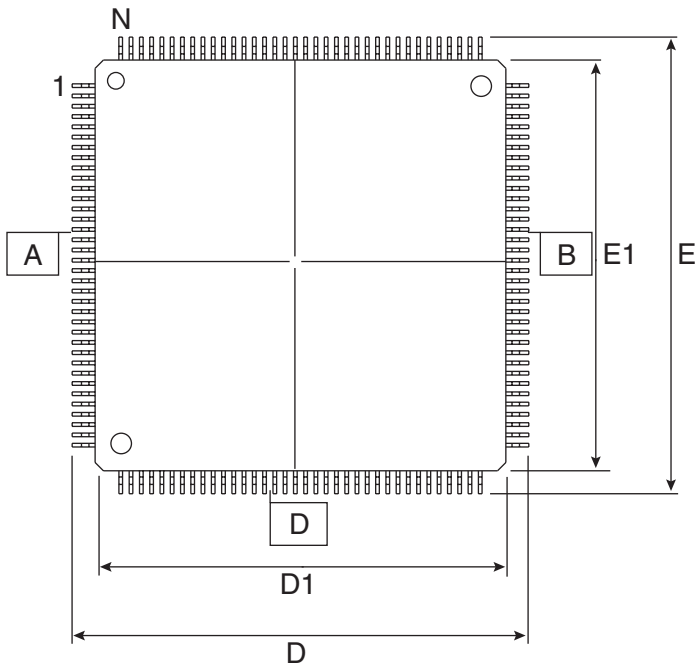
**Table 15-1.** Ordering Information

| Part Number    | Package                                | Temperature Range  | Screening | Comments                               |
|----------------|--|--|-----------|--|
| AT84AD004BCTD  | LQFP 144                               | C grade<br>$0^{\circ}\text{C} < T_{\text{amb}} < 70^{\circ}\text{C}$   | Standard  | Please contact your local sales office |
| AT84AD004BVTD  | LQFP 144                               | V grade<br>$-40^{\circ}\text{C} < T_{\text{amb}} < 85^{\circ}\text{C}$ | Standard  | Please contact your local sales office |
| AT84XAD004BEPW | LQFP-ep 144L<br>green (RoHS compliant) | Ambient  | Prototype |  |
| AT84AD004BCEPW | LQFP-ep 144L<br>green (RoHS compliant) | C grade<br>$0^{\circ}\text{C} < T_{\text{amb}} < 70^{\circ}\text{C}$   | Standard  |  |
| AT84AD004BVEPW | LQFP-ep 144L<br>green (RoHS compliant) | V grade<br>$-40^{\circ}\text{C} < T_{\text{amb}} < 85^{\circ}\text{C}$ | Standard  |  |
| AT84AD004TD-EB | LQFP 144                               | Ambient  | Prototype | Evaluation kit                         |



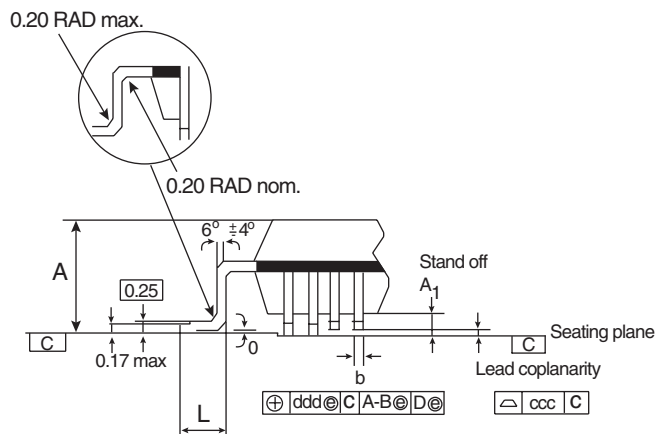
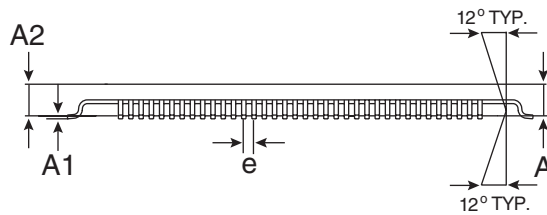
## 16. Packaging Information

Figure 16-1. LQFP 144 Package



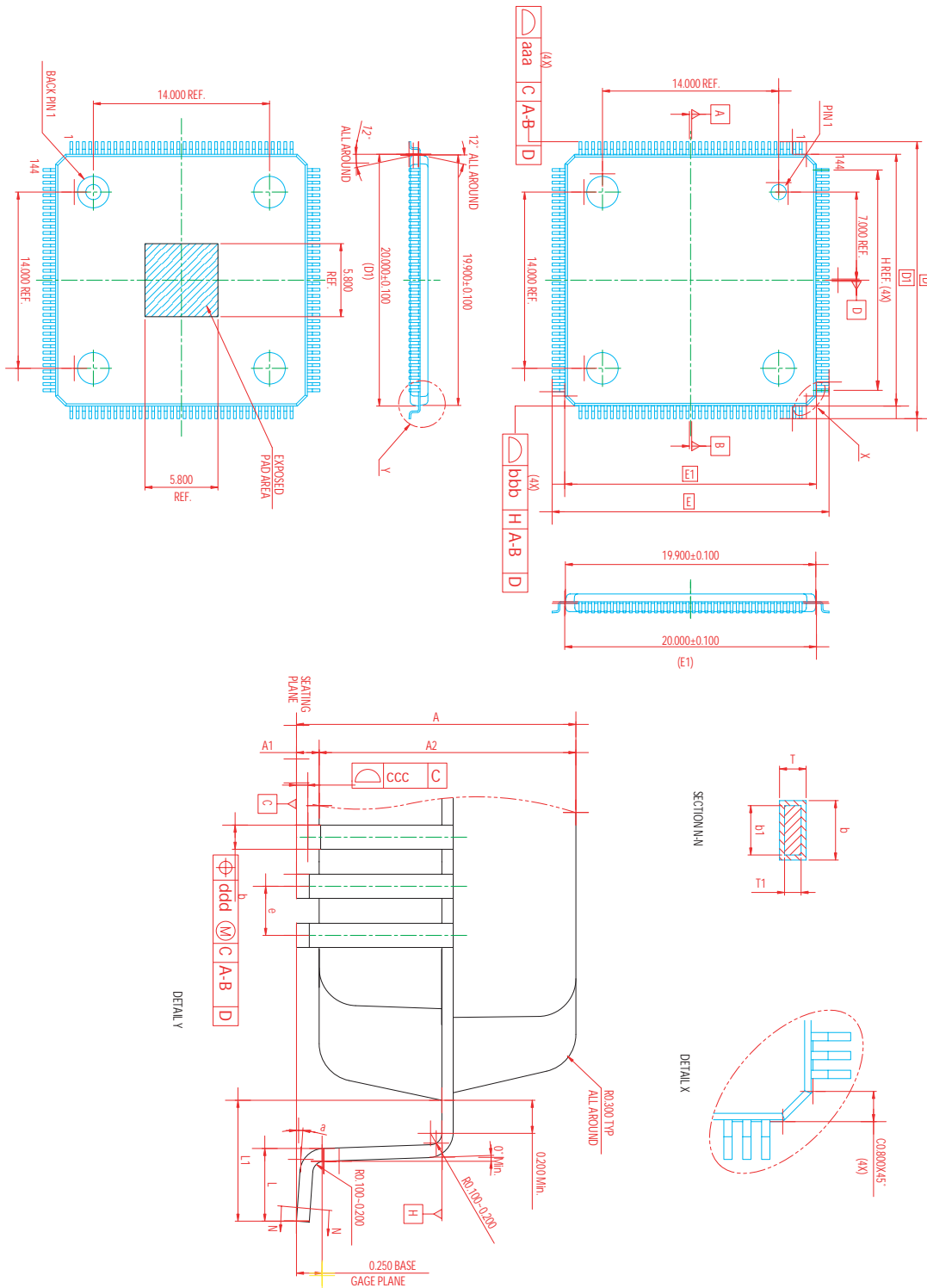
| Body +2.00 mm footprint |             |       |                     |
|-------------------------|-------------|-------|---------------------|
| Dims.                   | Tols.       | Leads | 144L                |
| A                       | max.        |       | 1.60                |
| A1                      |             |       | 0.05 min./0.15 max. |
| A2                      | +/- 0.05    |       | 1.40                |
| D                       | +/-0.20     |       | 22.00               |
| D1                      | +/-0.10     |       | 20.00               |
| E                       | +/-0.20     |       | 22.00               |
| E1                      | +/-0.10     |       | 20.00               |
| L                       | +0.15/-0.10 |       | 0.60                |
| e                       | basic       |       | 0.50                |
| b                       | +/-0.05     |       | 0.22                |
| ddd                     |             |       | 0.08                |
| ccc                     | max.        |       | 0.08                |
| o                       |             |       | 0°- 5°              |

- Notes:
1. All dimensions are in millimeters
  2. Dimensions shown are nominal with tolerances as indicated
  3. L/F: etfec 64T copper or equivalent
  4. Foot length: "L" is measured at gauge plane at 0.25 mm above the seating plane



Note: Thermally enhanced package: LQFP 144, 20 × 20 × 1.4 mm.

Figure 16-2. LQFP-ep 144L Green Package



DIMENSION LIST (FOOTPRINT: 2.00)

| S/N | SYM      | DIMENSIONS                                | REMARKS                   |
|-----|----------|---|---------------------------|
| 1   | A        | MAX. 1.600                                | OVERALL HEIGHT            |
| 2   | A1       | 0.100±0.050                               | STANDOFF                  |
| 3   | A2       | 1.400±0.050                               | PKG THICKNESS             |
| 4   | D        | 22.000±0.200                              | LEAD TIP TO TIP           |
| 5   | D1       | 20.000±0.100                              | PKG LENGTH                |
| 6   | E        | 22.000±0.200                              | LEAD TIP TO TIP           |
| 7   | E1       | 20.000±0.100                              | PKG WIDTH                 |
| 8   | L        | 0.600±0.150                               | FOOT LENGTH               |
| 9   | L1       | 1.000 REF.                                | LEAD LENGTH               |
| 10  | T        | 0.150 <sup>+0.050</sup> <sub>-0.050</sub> | LEAD THICKNESS            |
| 11  | T1       | 0.127±0.030                               | LEAD BASE METAL THICKNESS |
| 12  | a        | 0° ~ 7°                                   | FOOT ANGLE                |
| 13  | b        | 0.220±0.050                               | LEAD WIDTH                |
| 14  | b1       | 0.200±0.030                               | LEAD BASE METAL WIDTH     |
| 15  | e        | 0.500 BASE                                | LEAD PITCH                |
| 16  | H (REF.) | (17.500)                                  | CUM. LEAD PITCH           |
| 17  | aaa      | 0.200                                     | PROFILE OF LEAD TIPS      |
| 18  | bbb      | 0.200                                     | PROFILE OF MOLD SURFACE   |
| 19  | ccc      | 0.080                                     | FOOT COPLANARITY          |
| 20  | ddd      | 0.080                                     | FOOT POSITION             |

NOTES :

| S/N | DESCRIPTION   | SPECIFICATION |        |
|-----|---|---------------|--------|
| 1   | GENERAL TOLERANCE.  | DISTANCE      | ±0.100 |
|     |   | ANGLE         | ±2.5°  |
| 2   | MATTE FINISH ON PACKAGE BODY SURFACE EXCEPT EJECTION AND PIN 1 MARKING. | Ra0.8~2.0um   |        |
| 3   | ALL MOLDED BODY SHARP CORNER RADII UNLESS OTHERWISE SPECIFIED.          | MAX. R0.200   |        |
| 4   | PACKAGE/LEADFRAME MISALIGNMENT (X, Y):                                  | MAX. 0.127    |        |
| 5   | TOP/BTM PACKAGE MISALIGNMENT (X, Y):                                    | MAX. 0.127    |        |
| 6   | DRAWING DOES NOT INCLUDE PLASTIC OR METAL PROTRUSION OR CUTTING BURR.   |               |        |
| 7   | COMPLIANT TO JEDEC STANDARD:  | MS-026        |        |

FOR HIGH DENSITY STRIP LAYOUT

## Table of Contents

|           |   |           |
|-----------|---|-----------|
| <b>1</b>  | <b><i>Features</i></b> .....  | <b>1</b>  |
| <b>2</b>  | <b><i>Performance</i></b> .....   | <b>1</b>  |
| <b>3</b>  | <b><i>Application</i></b> .....   | <b>2</b>  |
| <b>4</b>  | <b><i>Description</i></b> .....   | <b>2</b>  |
| <b>5</b>  | <b><i>Functional Description</i></b> .....                                      | <b>2</b>  |
| <b>6</b>  | <b><i>Typical Applications</i></b> .....  | <b>4</b>  |
|           | 6.1 Absolute Maximum Ratings .....  | 5         |
|           | 6.2 Recommended Conditions of Use .....   | 6         |
| <b>7</b>  | <b><i>Electrical Operating Characteristics</i></b> .....                        | <b>6</b>  |
|           | 7.1 Timing Diagrams .....   | 12        |
|           | 7.2 Functions Description .....   | 19        |
|           | 7.3 Digital Output Coding (Nominal Settings) .....                              | 20        |
| <b>8</b>  | <b><i>Pin Description</i></b> .....   | <b>20</b> |
| <b>9</b>  | <b><i>Typical Characterization Results</i></b> .....                            | <b>22</b> |
|           | 9.1 Typical Full Power Input Bandwidth .....                                    | 23        |
|           | 9.2 Typical Crosstalk .....   | 23        |
|           | 9.3 Typical DC, INL and DNL Patterns .....                                      | 24        |
|           | 9.4 Typical Dynamic Performances Versus Sampling Frequency .....                | 25        |
|           | 9.5 Typical Dynamic Performances Versus Input Frequency .....                   | 26        |
|           | 9.6 Typical Signal Spectrum .....   | 28        |
|           | 9.7 Typical Performance Sensitivity Versus Power Supplies and Temperature ..... | 30        |
| <b>10</b> | <b><i>Test and Control Features</i></b> .....                                   | <b>34</b> |
|           | 10.1 3-wire Serial Interface Control Setting .....                              | 34        |
|           | 10.2 Die Junction Temperature Monitoring Function .....                         | 42        |
|           | 10.3 VtestI, VtestQ .....   | 42        |
| <b>11</b> | <b><i>Equivalent Input/Output Schematics</i></b> .....                          | <b>43</b> |
| <b>12</b> | <b><i>Definitions of Terms</i></b> .....  | <b>45</b> |
| <b>13</b> | <b><i>Using the AT84AD004B Dual 8-bit 500 Msps ADC</i></b> .....                | <b>47</b> |
|           | 13.1 Decoupling, Bypassing and Grounding of Power Supplies .....                | 47        |
|           | 13.2 Analog Input Implementation .....  | 48        |

|           |  |           |
|-----------|--|-----------|
| 13.3      | Clock Implementation .....                                     | 49        |
| 13.4      | Reset Implementation .....                                     | 50        |
| 13.5      | Output Termination in 1:1 Ratio .....                          | 51        |
| 13.6      | Using the Dual ADC With and ASIC/FPGA Load .....               | 52        |
| <b>14</b> | <b><i>Thermal Characteristics</i></b> .....                    | <b>53</b> |
| 14.1      | Simplified Thermal Model for LQFP 144 (20 × 20 × 1.4 mm) ..... | 53        |
| 14.2      | LQFP-ep 144L Green Package Thermal Characteristics .....       | 54        |
| <b>15</b> | <b><i>Ordering Information</i></b> .....                       | <b>56</b> |
| <b>16</b> | <b><i>Packaging Information</i></b> .....                      | <b>57</b> |
|           | <b><i>Table of Contents</i></b> .....                          | <b>1</b>  |



## How to reach us

Home page: [www.e2v.com](http://www.e2v.com)

### Sales offices:

#### Europe Regional sales office

##### e2v ltd

106 Waterhouse Lane  
Chelmsford Essex CM1 2QU  
England  
Tel: +44 (0)1245 493493  
Fax: +44 (0)1245 492492  
mailto: [enquiries@e2v.com](mailto:enquiries@e2v.com)

##### e2v sas

16 Burospace  
F-91572 Bièvres Cedex  
France  
Tel: +33 (0) 16019 5500  
Fax: +33 (0) 16019 5529  
mailto: [enquiries-fr@e2v.com](mailto:enquiries-fr@e2v.com)

##### e2v gmbh

Industriestraße 29  
82194 Gröbenzell  
Germany  
Tel: +49 (0) 8142 41057-0  
Fax: +49 (0) 8142 284547  
mailto: [enquiries-de@e2v.com](mailto:enquiries-de@e2v.com)

#### Americas

##### e2v inc

520 White Plains Road  
Suite 450 Tarrytown, NY 10591  
USA  
Tel: +1 (914) 592 6050 or 1-800-342-5338,  
Fax: +1 (914) 592-5148  
mailto: [enquiries-na@e2v.com](mailto:enquiries-na@e2v.com)

#### Asia Pacific

##### e2v ltd

11/F.,  
Onfem Tower,  
29 Wyndham Street,  
Central, Hong Kong  
Tel: +852 3679 364 8/9  
Fax: +852 3583 1084  
mailto: [enquiries-ap@e2v.com](mailto:enquiries-ap@e2v.com)

#### Product Contact:

e2v  
Avenue de Rochepleine  
BP 123 - 38521 Saint-Egrève Cedex  
France  
Tel: +33 (0)4 76 58 30 00  
**Hotline:**  
mailto: [hotline-bdc@e2v.com](mailto:hotline-bdc@e2v.com)

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